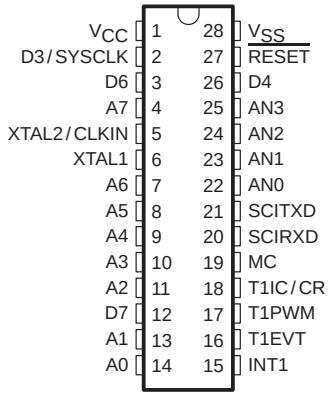
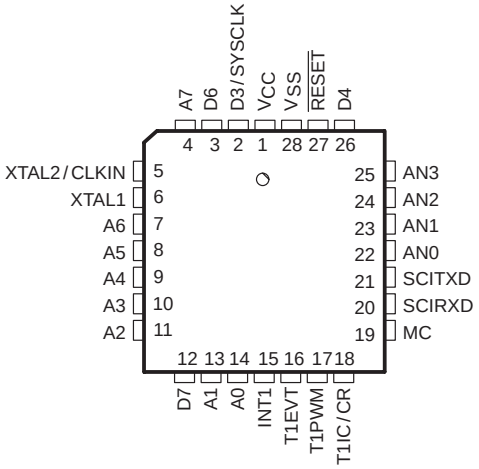
- **CMOS/EEPROM/EPROM Technologies on a Single Device**
  - **Mask-ROM Devices for High-Volume Production**
  - **One-Time-Programmable (OTP) EPROM Devices for Low Volume Production**
  - **Reprogrammable EPROM Devices for Prototyping Purposes**
- **Internal System Memory Configurations**
  - **On-Chip Program Memory Versions**
    - **ROM: 4K Bytes**
    - **EPROM: 8K Bytes**
  - **Static RAM: 128 Bytes**
- **Flexible Operating Features**
  - **Low-Power Modes: STANDBY and HALT**
  - **Commercial, Industrial, and Automotive Temperature Ranges**
  - **Clock Options**
    - **Divide-by-4 (0.5 to 5 MHz SYSCLK)**
    - **Divide-by-1 (2 to 5 MHz SYSCLK) PLL**
  - **Supply Voltage (V_{CC}) 5 V ±10%**
- **Four-Channel 8-Bit Analog-to-Digital Converter 2 (ADC2)**
- **16-Bit General-Purpose Timer**
  - **Software Configurable as a 16-Bit Event Counter, or a 16-Bit Pulse Accumulator, or a 16-Bit Input Capture Function, or Two Compare Registers, or a Self-Contained Pulse-Width-Modulation (PWM) Function**
- **On-Chip 24-Bit Watchdog Timer**
  - **EPROM/OTP Devices: Standard Watchdog**
  - **Mask-ROM Devices: Hard Watchdog, Simple Counter, or Standard Watchdog**
- **Flexible Interrupt Handling**
- **Workstation/Personal Computer-Based Development System**
  - **C Compiler and C Source Debugger**
  - **Real-Time In-Circuit Emulation**
  - **Extensive Breakpoint/Trace Capability**
  - **Software Performance Analysis**
  - **Multi-Window User Interface**
  - **Microcontroller Programmer**
- **Serial Communications Interface 2 (SCI2)**
  - **Asynchronous Mode: 156 Kbps Maximum at 5 MHz SYSCLK**
  - **Full Duplex, Double-Buffered Receiver (RX) and Transmitter (TX)**
- **TMS370 Series Compatibility**
  - **Register-to-Register Architecture**
  - **256 General-Purpose Registers**
  - **14 Powerful Addressing Modes**
  - **Instructions Upwardly Compatible With All TMS370 Devices**
- **CMOS/TTL Compatible I/O Pins/Packages**
  - **All Peripheral Function Pins Software Configurable for Digital I/O**
  - **17 Bidirectional Pins, 5 Input Pins**
  - **28-Pin Plastic and Ceramic Dual-In-Line, or Leaded Chip Carrier Packages**

JD AND N PACKAGES
(TOP VIEW)



FZ AND FN PACKAGES
(TOP VIEW)



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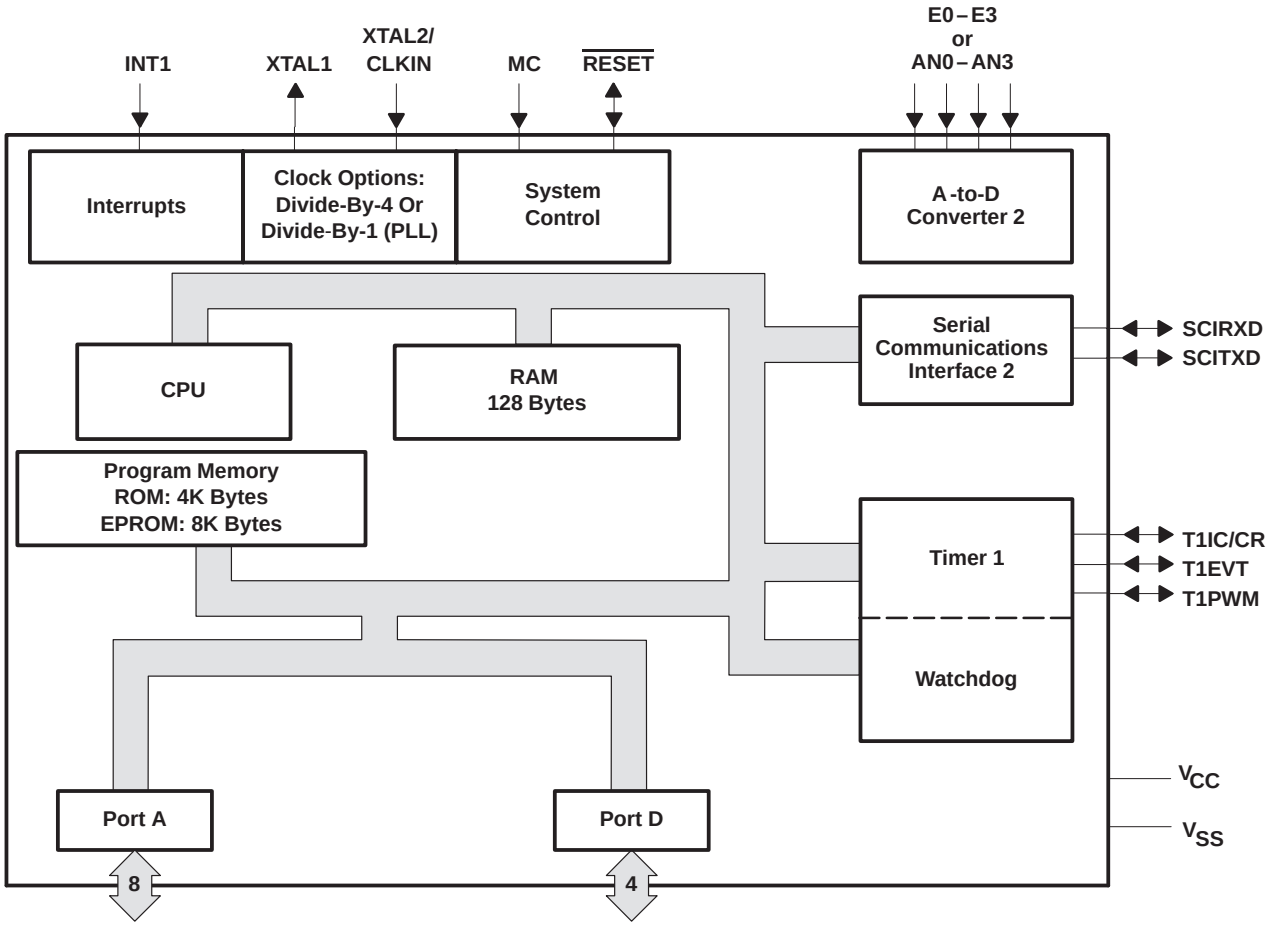
Pin Descriptions

28 PINS DIP and LCC		I/O†	DESCRIPTION
NAME	NO.		
A0 A1 A2 A3 A4 A5 A6 A7	14 13 11 10 9 8 7 4	I / O	Port A is a general-purpose bidirectional I/O port.
D3/SYSCLK D4 D6 D7	2 26 3 12	I / O	Port D is a general-purpose bidirectional I/O port. D3 is also configurable as SYSCLK.
INT1	15	I	External interrupt (non-maskable or maskable)/general-purpose input pin.
AN0/E0 AN1/E1 AN2/E2 AN3/E3	22 23 24 25	I	ADC2 module analog input (AN0–AN3) or positive reference pins (AN1–AN3). Port E can be individually programmed as general-purpose input pins if not used as ADC2 analog input.
T1IC/CR T1PWM T1EVT	18 17 16	I / O	Timer1 input capture/counter reset input pin /general-purpose bidirectional pin. Timer1 PWM output pin/general-purpose bidirectional pin. Timer1 external event input pin/general-purpose bidirectional pin.
SCITXD SCIRXD	21 20	I / O	SCI module transmit data output/general-purpose bidirectional pin. (See Note 1) SCI module receive data input pin/general-purpose bidirectional pin.
$\overline{\text{RESET}}$	27	I / O	System reset bidirectional pin; as input pin, $\overline{\text{RESET}}$ initializes the microcontroller; as open-drain output, $\overline{\text{RESET}}$ indicates that an internal failure was detected by watchdog or oscillator fault circuit.
MC	19	I	Mode control input pin; programming EPROM when V_{PP} is applied to MC pin.
XTAL2/CLKIN XTAL1	5 6	I O	Internal oscillator crystal input/External clock source input. Internal oscillator output for crystal.
V_{CC}	1		Positive supply voltage
V_{SS}	28		Ground reference

† I = input, O = output

NOTE 1: The two SCI configuration pins are referenced to as SCI2.

functional block diagram



description

The TMS370C3C0, TMS370C6C2, and SE370C6C2 devices are members of the TMS370 family of single-chip 8-bit microcontrollers. Unless otherwise noted, the term TMS370CxCx refers to these devices. The TMS370 family provides cost-effective real-time system control through integration of advanced peripheral function modules and various on-chip memory configurations.

The TMS370CxCx family of devices is implemented using high-performance silicon-gate CMOS EPROM technologies. Low-operating power, wide-operating temperature range, and noise immunity of CMOS technology coupled with the high performance and extensive on-chip peripheral functions make the TMS370CxCx devices attractive in system designs for automotive electronics, industrial motors, computer peripheral controls, telecommunications, and consumer applications.

All TMS370CxCx devices contain the following on-chip peripheral modules:

- Four-channel, 8-bit analog to digital converter 2 (ADC2)
- Serial communications interface 2 (SCI2)
- One 24-bit general-purpose watchdog timer
- One 16-bit general-purpose timer with an 8-bit prescaler

description (continued)

Table 1 provides a memory configuration overview of the TMS370CxCx devices.

Table 1. Memory Configurations

DEVICES	PROGRAM MEMORY (BYTES)		DATA MEMORY (BYTES)		PACKAGES 28-PIN LCC OR DIP
	ROM	EPROM	RAM	EEPROM	
TMS370C3C0A	4K	—	128	—	FN – PLCC N – PDIP
TMS370C6C2A	—	8K	128	—	FN – PLCC N – PDIP
SE370C6C2A†	—	8K	128	—	FZ – CLCC JD – CDIP

† System evaluators and development are for use only in prototype environment, and their reliability has not been characterized.

The suffix letter (A) appended to the device name (shown in Table 1) indicates configuration of the device. ROM or EPROM devices have different configurations as indicated in Table 2. ROM devices with the suffix letter A are configured through a programmable contact during manufacture.

Table 2. Suffix Letter Configuration

DEVICE	WATCHDOG TIMER	CLOCK	LOW-POWER MODE
EPROM A	Standard	Divide-by-4 (standard oscillator)	Enabled
ROM A	Standard	Divide-by-4 or Divide-by-1 (PLL)	Enabled or disabled
	Hard		
	Simple		

The 4K bytes of mask-programmable ROM in the associated TMS370C3C0A device are replaced in the TMS370C6C2A with 8K bytes of EPROM while all other available memory and on-chip peripherals are identical. The one-time programmable (OTP) (TMS370C6C2A) and reprogrammable (SE370C6C2A) devices are available.

TMS370C6C2A OTP devices are available in plastic packages. This microcontroller is effective to use for immediate production updates for other members of the TMS370C3C0A or for low-volume production runs when the mask charge or cycle time for the low-cost mask ROM devices is not practical.

The SE370C6C2A has a windowed ceramic package to allow reprogramming of the program EPROM memory during the development-prototyping phase of design. The SE370C6C2A devices allow quick updates to breadboards and prototype systems during initial design iterations.

The TMS370CxCx family provides two low-power modes (STANDBY and HALT) for applications where low-power consumption is critical. Both modes stop all CPU activity, that is, no instructions are executed. In the STANDBY mode, the internal oscillator and the general-purpose timer remain active. In the HALT mode, all device activity is stopped. The device retains all RAM data and peripheral configuration bits throughout both low-power modes.

The TMS370CxCx features advanced register-to-register architecture that allows direct arithmetic and logical operations without requiring an accumulator (for example, ADD R24, R47; add the contents of register 24 to the contents of register 47 and store the result in register 47). The TMS370CxCx family is fully instruction-set compatible, providing easy transition between members of the TMS370 8-bit microcontroller family.

description (continued)

The TMS370CxCx device has one operational mode of serial communications provided by the SCI2 module. The SCI2 allows standard RS-232-C communications with other common data transmission equipment.

The TMS370CxCx family provides the system designer with economical, efficient solutions to real-time control applications. The TMS370 family compact development tool (CDT™) solves the challenge of efficiently developing the software and hardware required to design the TMS370CxCx into an ever-increasing number of complex applications. The application source code can be written in assembly and C-language, and the output code can be generated by the linker. The TMS370 family CDT development tool can communicate through a standard RS-232-C interface with an existing personal computer. This allows the use of the personal computer editors and software utilities already familiar to the designer. The TMS370 family CDT emphasizes ease-of-use through extensive menus and screen windowing so that a system designer can begin developing software with minimal training. Precise real-time in-circuit emulation and extensive symbolic debug and analysis tools ensure efficient software and hardware implementation as well as reduced time-to-market cycle.

The TMS370CxCx family together with the TMS370 family CDT370, software tools, the SE370C6C2A reprogrammable devices, comprehensive product documentation, and customer support provide a complete solution to the needs of the system designer.

central processing unit (CPU)

The CPU used on the TMS370CxCx device is the high-performance 8-bit TMS370 CPU module. The ’xCx implements an efficient register-to-register architecture that eliminates the conventional accumulator bottleneck. The complete ’xCx instruction map is shown in Table 36 in the TMS370CxCx instruction set overview section.

The ’370CxCx CPU architecture provides the following components:

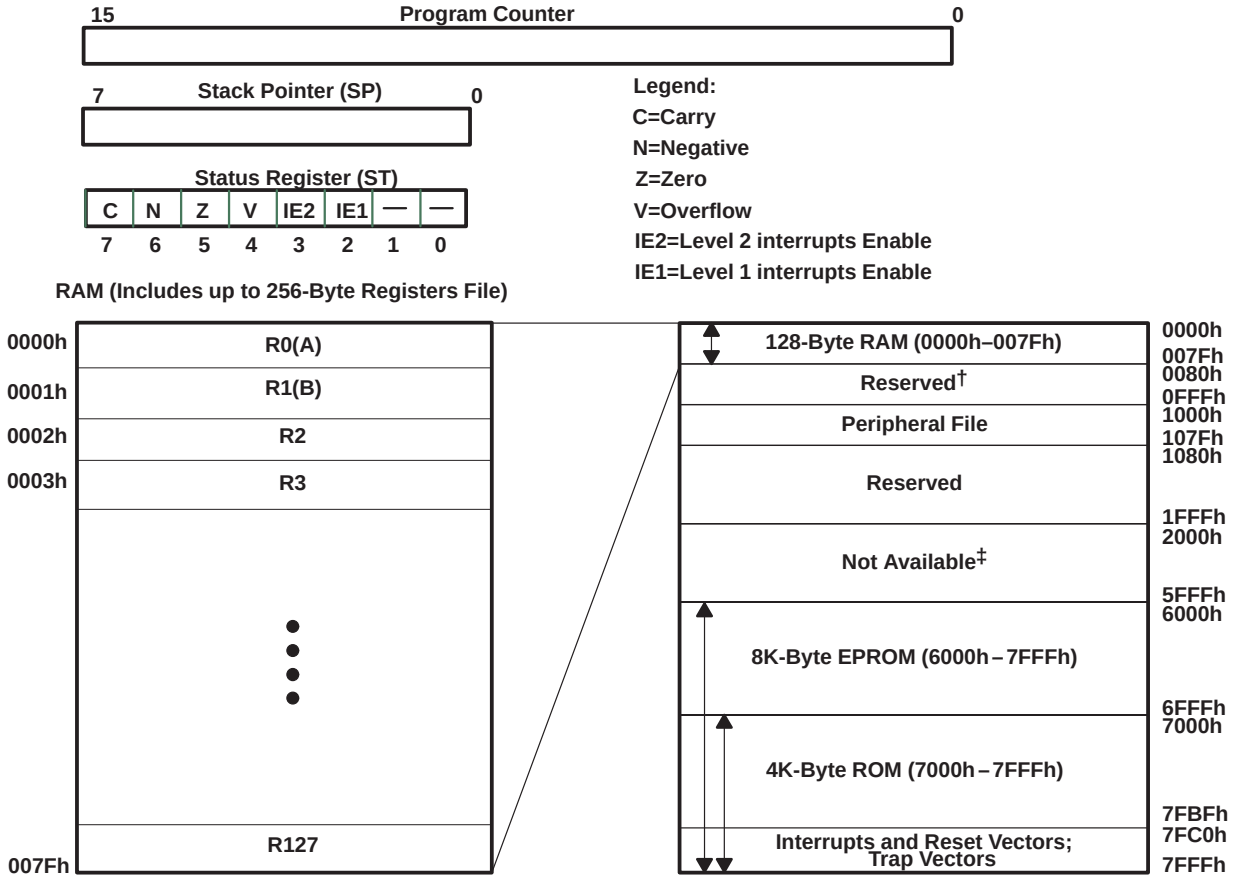
CPU registers:

- A stack pointer that points to the last entry in the memory stack.
- A status register that monitors the operation of the instructions and contains the global-interrupt enable bits.
- A program counter (PC) that points to the memory location of the next instruction to be executed.

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central processing unit (CPU) (continued)

Figure 1 illustrates the CPU registers and memory blocks.



† Reserved means the address space is reserved for future expansion.
‡ Not available means the address space is not accessible.

Figure 1. Programmer's Model

A memory map that includes:

- 128-byte general-purpose RAM that can be used for data memory storage, program instructions, general-purpose register, or the stack
- A peripheral file that provides access to all internal peripheral modules, system-wide control functions and EPROM programming control
- 4K-byte ROM or 8K-byte EPROM program memory

stack pointer (SP)

The SP is an 8-bit CPU register that operates as a last-in, first-out, read/write memory. Typically, the stack is used to store the return address on subroutine calls as well as the status-register contents during interrupt sequences.

The SP points to the last entry or top of the stack. The SP is incremented automatically before data is pushed onto the stack and decremented after data is popped from the stack. The stack can be placed anywhere in the on-chip RAM.

central processing unit (CPU) (continued)

status register (ST)

The ST monitors the operation of the instructions and contains the global interrupt-enable bits. The ST register includes four status bits (condition flags) and two interrupt-enable bits:

- The four status bits indicate the outcome of the previous instruction; conditional instructions (for example, the conditional jump instructions) use the status bits to determine program flow.
- The two interrupt-enable bits control the two interrupt levels.

The ST register, status-bit notation, and status-bit definitions are shown in Table 3.

Table 3. Status Register (ST)

7	6	5	4	3	2	1	0
C	N	Z	V	IE2	IE1	Reserved	Reserved
RW-0	RW-0	RW-0	RW-0	RW-0	RW-0		

R = read, W = write, 0 = value after reset

program counter (PC)

The contents of the PC point to the memory location of the next instruction to be executed. The PC consists of two 8-bit registers in the CPU: the program counter high (PCH) and program counter low (PCL). These registers contain the most significant byte (MSbyte) and least significant byte (LSbyte) of a 16-bit address.

During reset, the contents of the reset vector (7FFEh, 7FFFh) are loaded into the program counter. The PCH (MSbyte of the PC) is loaded with the contents of memory location 7FFEh, and the PCL (LSbyte of the PC) is loaded with the contents of memory location 7FFFh. Figure 2 shows this operation using an example value of 7000h as the contents of the reset vector.

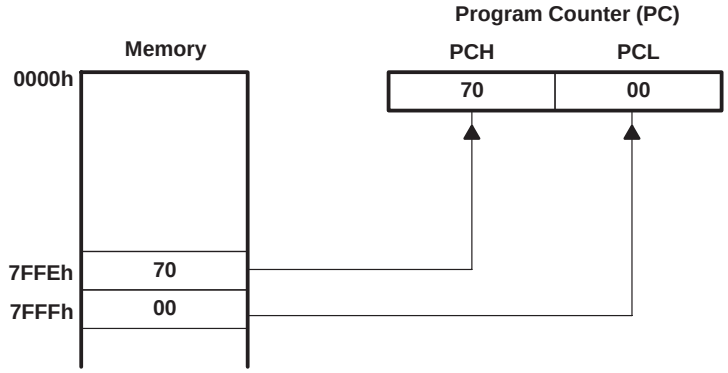


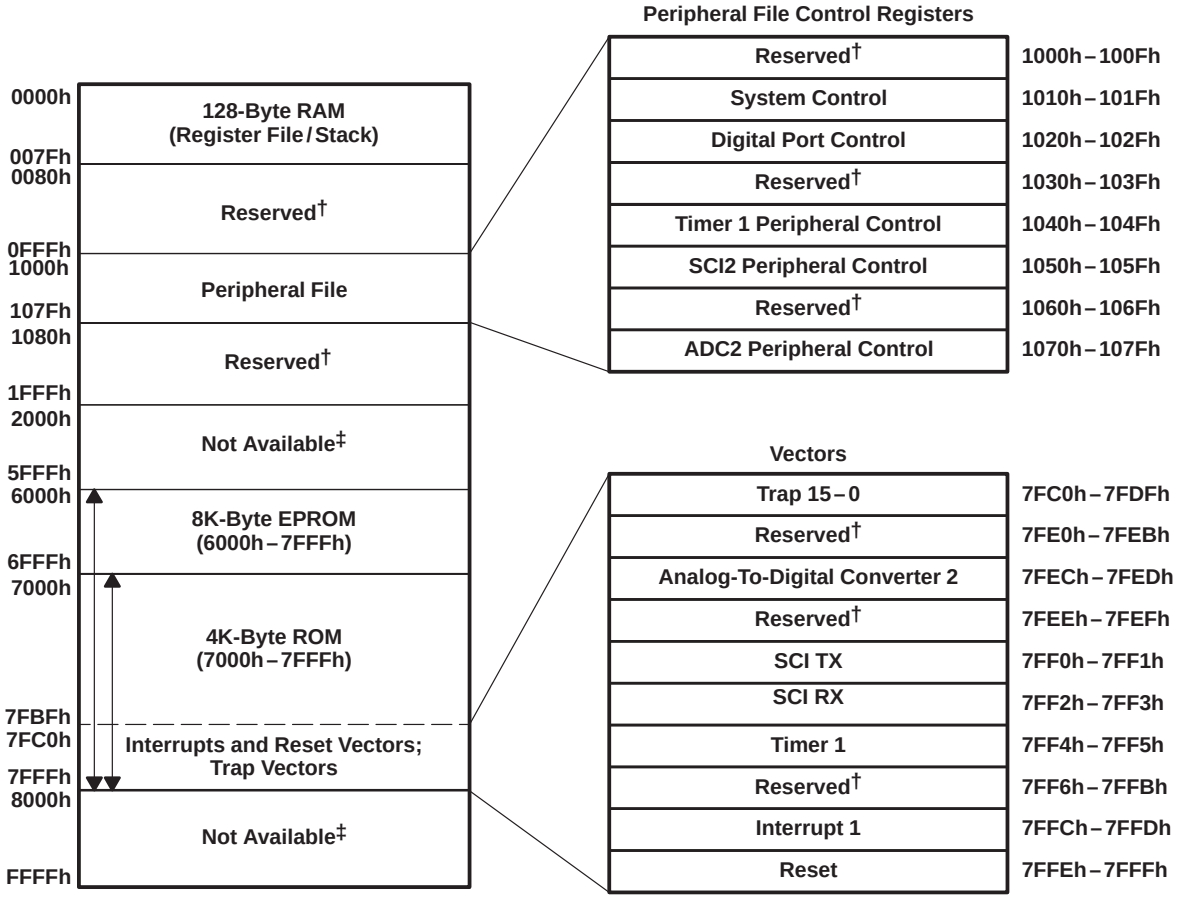
Figure 2. Program Counter After Reset

memory map

The TMS370CxCx architecture is based on the Von Neuman architecture, where the program memory and data memory share a common address space. All peripheral input/output is memory mapped in this same common address space. As shown in Figure 3, the TMS370CxCx provides memory-mapped RAM, ROM, input/output pins, peripheral functions, and system interrupt vectors.

The peripheral file contains all input/output port control, peripheral status and control, EPROM, and system-wide control functions. The peripheral file is located from 1000h to 107Fh and is logically divided into seven peripheral file frames of 16 bytes each. Each on-chip peripheral is assigned to a separate frame through which peripheral control and data information is passed.

memory map (continued)



† Reserved means the address space is reserved for future expansion.
‡ Not available means the address space is not accessible.

Figure 3. TMS370CxCx Memory Map

RAM/register file (RF)

Locations within the RAM address space can serve as the RF, general-purpose read/write memory, program memory, or the stack instructions. The TMS370CxCx devices contain 128 bytes of internal RAM mapped beginning at location 0000h (R0) and continuing through location 007Fh (R127) which is shown in Figure 1.

The first two registers, R0 and R1, are also called register A and B, respectively. Some instructions implicitly use register A or B; for example, the instruction LDSP (load SP) assumes that the value to be loaded into the SP is contained in register B. Registers A and B are the only registers cleared on reset.

peripheral file (PF)

The TMS370CxCx control registers contain all the registers necessary to operate the system and peripheral modules on the device. The instruction set includes some instructions that access the PF directly. These instructions designate the register by the number of the PF relative to 1000h, preceded by P0 for a hexadecimal designator or P for a decimal designator. For example, the system control register 0 (SCCR0) is located at address 1010h; its peripheral file hexadecimal designator is P010, and its decimal designator is P16. Table 4 shows the TMS370CxCx PF address map.

peripheral file (PF) (continued)

Table 4. TMS370CxCx Peripheral File Address Map

ADDRESS RANGE	PERIPHERAL FILE DESIGNATOR	DESCRIPTION
1000h–100Fh	P000–P00F	Reserved
1010h–101Fh	P010–P01F	System and EPROM control registers
1020h–102Fh	P020–P02F	Digital I/O port control registers
1030h–103Fh	P030–P03F	Reserved
1040h–104Fh	P040–P04F	Timer 1 registers
1050h–105Fh	P050–P05F	Serial communications interface 2 registers
1060h–106Fh	P060–P06F	Reserved
1070h–107Fh	P070–P07F	Analog-to-digital converter 2 registers
1080h–1FFFh	P080–P0FF	Reserved

program EPROM†

The TMS370C6C2 device contains 8K bytes of EPROM mapped at location 6000h and continuing through location 7FFFh as shown in Figure 3. Reading the program EPROM modules is identical to reading other internal memory. During programming, the EPROM is controlled by the EPROM control register (EPCTL). The program EPROM module features include:

- Programming
  - In-circuit programming capability if V_{PP} is applied to MC
  - Control register: EPROM programming is controlled by the EPROM control register (EPCTL) located in the peripheral file (PF) frame at location P01Ch as shown in Table 5.
- Write protection: Writes to the program EPROM are disabled under the following conditions:
  - Reset halts all programming to the EPROM module.
  - Low-power modes
  - 13 V not applied to MC

Table 5. Data EEPROM and Program EPROM Control Registers Memory Map

ADDRESS	SYMBOL	NAME
P01A to P01B	—	Reserved
P01C	EPCTL	Program EPROM Control Register

program ROM†

The program read-only memory (ROM) consists of 4K bytes of mask-programmable ROM. The program ROM is used for permanent storage of data or instructions. Programming of the mask ROM is performed at the time of device fabrication. Refer to Figure 3 for ROM memory map.

† Memory addresses 7FE0h through 7FEBh are reserved for Texas Instruments, and addresses 7FECh through 7FFFh are reserved for interrupt and reset vectors. Trap vectors, used with TRAP0 through TRAP15 instructions, are located between addresses 7FC0h and 7FDFh.

system reset

The system reset operation ensures an orderly start-up sequence for the TMS370CxCx CPU-based device. There are up to three different actions that can cause a system reset to the device. Two of these actions are internally generated, while one ($\overline{\text{RESET}}$ pin) is controlled externally. These actions are as follows:

- External $\overline{\text{RESET}}$ pin. A low level signal can trigger an external reset. To ensure a reset, the external signal should be held low for one SYSCLK cycle. Signals of less than one SYSCLK can generate a reset. See the *TMS370 User's Guide* (literature number SPNU127) for more information.
- Watchdog (WD) timer. A watchdog-generated reset occurs if an improper value is written to the WD key register, or if the re-initialization does not occur before the watchdog timer timeout . See the *TMS370 User's Guide* (literature number SPNU127) for more information.
- Oscillator reset. Reset occurs when the oscillator operates outside of the recommended operating range. See the *TMS370 User's Guide* (literature number SPNU127) for more information.

Once a reset source is activated, the external $\overline{\text{RESET}}$ pin is driven low (active) for a minimum of eight SYSCLK cycles. This allows the 'xCx device to reset external system components. Additionally, if a cold start (V_{CC} is off for several hundred milliseconds) condition or oscillator failure occurs or the $\overline{\text{RESET}}$ pin is held low, then the reset logic holds the device in a reset state for as long as these actions are active.

After a reset, the program can check the oscillator fault flag (OSC FLT FLAG, SCCR0.4), the cold start flag (COLD START, SCCR0.7) and the watchdog reset (WD OVRFL INT FLAG, T1CTL2.5) to determine the source of the reset. A reset does not clear these flags. Table 6 lists the reset sources.

Table 6. Reset Sources

REGISTER	ADDRESS	PF	BIT NO.	CONTROL BIT	SOURCE OF RESET
SCCR0	1010h	P010	7	COLD START	Cold (power-up)
SCCR0	1010h	P010	4	OSC FLT FLAG	Oscillator out of range
T1CTL2	104Ah	P04A	5	WD OVRFL INT FLAG	Watchdog timer timeout

Once a reset is activated, the following sequence of events occurs:

1. CPU registers are initialized: ST = 00h, SP = 01h (reset state).
2. Registers A and B are initialized to 00h (no other RAM is changed).
3. The contents of the LSbyte of the reset vector (07FFh) are read and stored in the PCL.
4. The contents of the MSbyte of the reset vector (07FEh) are read and stored in the PCH.
5. Program execution begins with an opcode fetch from the address pointed to the PC.

The reset sequence takes 20 SYSCLK cycles from the time the reset pulse is released until the first opcode fetch. During a reset, RAM contents (except for registers A and B) remain unchanged, and the module control register bits are initialized to their reset state.

interrupts

The TMS370 family software programmable interrupt structure permits flexible on-chip and external interrupt configurations to meet real-time interrupt-driven application requirements. The hardware interrupt structure incorporates two priority levels as shown in Figure 4. Interrupt level 1 has a higher priority than interrupt level 2. The two priority levels can be masked independently by the global-interrupt mask bits (IE1 and IE2) of the status register.

interrupts (continued)

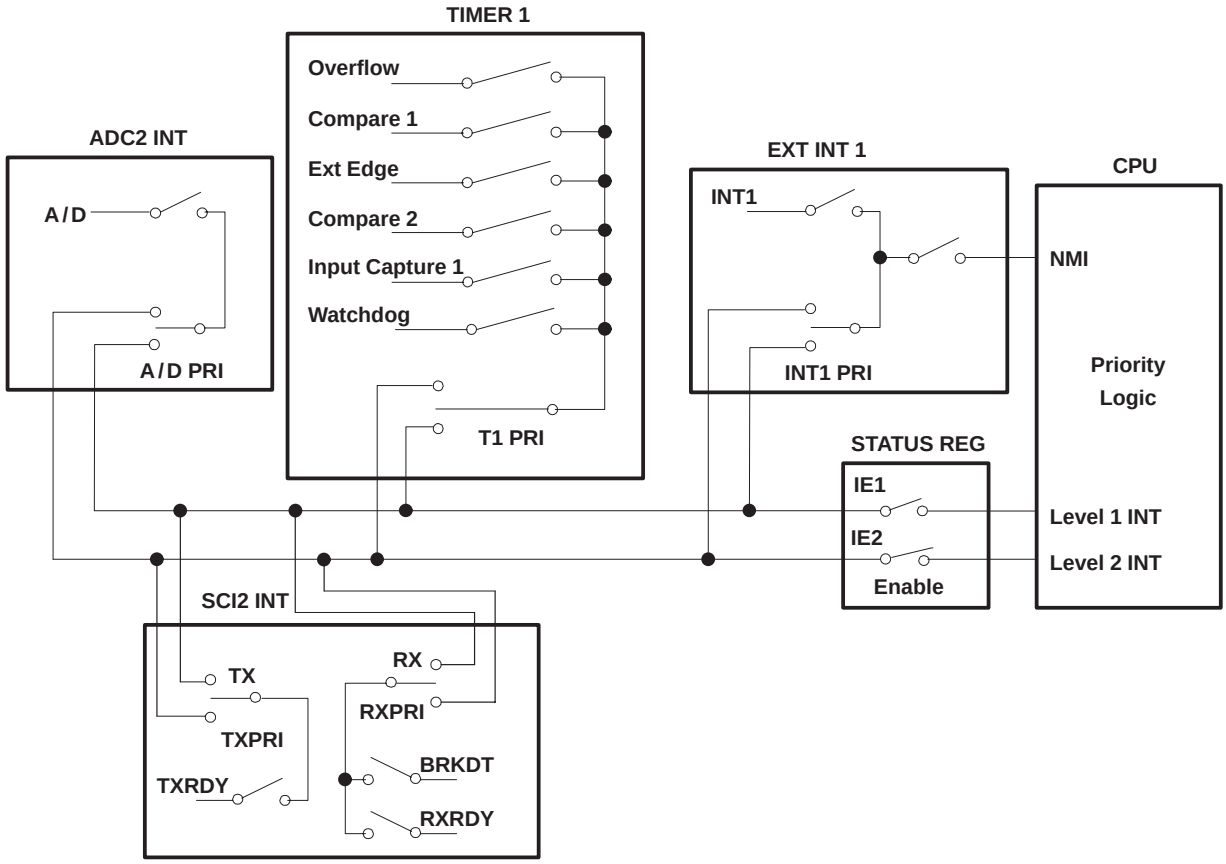


Figure 4. Interrupt Control

Each system interrupt is configured independently to either the high- or low-priority chain by the application program during system initialization. Within each interrupt chain, the interrupt priority is fixed by the position of the system interrupt. However, since each system interrupt is selectively configured on either the high- or low-priority interrupt chain, the application program can elevate any system interrupt to the highest priority. Arbitration between the two priority levels is performed within the CPU. Arbitration within each of the priority chains is performed within the peripheral modules to support interrupt expansion for future modules. Pending-interrupts are serviced upon completion of current instruction execution, depending on their interrupt mask and priority conditions.

The TMS370CxCx has five hardware system interrupts (plus $\overline{\text{RESET}}$) as shown in Table 7. Each system interrupt has a dedicated vector located in program memory through which control is passed to the interrupt service routines. A system interrupt may have multiple interrupt sources (for example, SCI RXINT has two interrupt sources). All of the interrupt sources are individually maskable by local interrupt-enable control bits in the associated peripheral file. Each interrupt source FLAG bit is readable individually for software polling or for determining which interrupt source generated the associated system interrupt.

Four of the system interrupts are generated by on-chip peripheral functions, and one external interrupt is supported. Software configuration of the external interrupts is performed through the INT1 control register in peripheral file frame 1. Each external interrupt is individually software configurable for input polarity (rising or falling edge) for ease of system interface. External interrupt INT1 is software configurable as either a maskable or non-maskable interrupt. When INT1 is configured as non-maskable, it cannot be masked by the individual-

interrupts (continued)

or global-enable mask bits. The INT1 NMI bit is protected during non-privileged operation and therefore should be configured during the initialization sequence following reset. To maximize pin flexibility, external interrupt INT1 can be software-configured as a general-purpose input pin if the interrupt function is not required.

Table 7. Hardware System Interrupts

INTERRUPT SOURCE	INTERRUPT FLAG	SYSTEM INTERRUPT	VECTOR ADDRESS	PRIORITY†
External $\overline{\text{RESET}}$ Watchdog Overflow Oscillator Fault Detect	COLD START WD OVRFL INT FLAG OSC FLT FLAG	$\overline{\text{RESET}}$‡	7FFEh, 7FFFh	1
External INT1	INT1 FLAG	INT1‡	7FFCh, 7FFDh	2
Timer 1 Overflow Timer 1 Compare 1 Timer 1 Compare 2 Timer 1 External Edge Timer 1 Input Capture 1 Watchdog Overflow	T1 OVRFL INT FLAG T1C1 INT FLAG T1C2 INT FLAG T1EDGE INT FLAG T1IC1 INT FLAG WD OVRFL INT FLAG	T1INT§	7FF4h, 7FF5h	3
SCI RX Data Register Full SCI RX Break Detect	RXRDY FLAG BRKDT FLAG	RXINT‡	7FF2h, 7FF3h	4
SCI TX Data Register Empty	TXRDY FLAG	TXINT	7FF0h, 7FF1h	5
A/D Conversion Complete	AD INT FLAG	ADINT	7FECh, 7FEDh	6

† Relative priority within an interrupt level.
‡ Release microcontroller from STANDBY and HALT low-power modes.
§ Release microcontroller from STANDBY low-power mode.

privileged operation and EEPROM write-protection override

The TMS370CxCx family has significant flexibility to enable the designer to software configure the system and peripherals to meet the requirements of a variety of applications. The non-privileged mode of operation ensures the integrity of the system configuration, once it is defined for an application. Following a hardware reset, the TMS370CxCx operates in the privileged mode, where all peripheral file registers have unrestricted read/write access, and the application program configures the system during the initialization sequence following reset. As the last step of system initialization, the PRIVILEGE DISABLE bit (SCCR2.0) is set to 1 to enter the non-privileged mode; thus, disabling write operations to specific configuration control bits within the peripheral file. Table 8 displays the system configuration bits which are write-protected during the non-privileged mode and must be configured by software prior to exiting the privileged mode.

privileged operation and EEPROM write-protection override (continued)

Table 8. Privilege Bits

REGISTER†		CONTROL BIT
NAME	LOCATION	
SCCR0	P010.5 P010.6	PF AUTO WAIT OSC POWER
SCCR1	P011.2 P011.4	MEMORY DISABLE AUTOWAIT DISABLE
SCCR2	P012.0 P012.1 P012.3 P012.4 P012.6 P012.7	PRIVILEGE DISABLE INT1 NMI CPU STEST BUS STEST PWRDWN/IDLE HALT/STANDBY
T1PRI	P04F.6 P04F.7	T1 PRIORITY TI STEST
SCIPRI	P05F.4 P05F.5 P05F.6 P05F.7	SCI ESPEN SCIRX PRIORITY SCITX PRIORITY SCI STEST
ADPRI	P07F.5 P07F.6 P07F.7	AD ESPEN AD PRIORITY AD STEST

† The privilege bits are shown in a bold typeface in the peripheral file frame 1 section.

low-power and IDLE modes

The TMS370CxCx devices have two low-power modes (STANDBY and HALT) and an IDLE mode. For mask-ROM devices, low-power modes can be disabled permanently through a programmable contact at the time when the mask is manufactured.

The STANDBY and HALT low-power modes significantly reduce power consumption by reducing or stopping the activity of the various on-chip peripherals when processing is not required. Each of the low-power modes is entered by executing the IDLE instruction when the PWRDWN/IDLE bit in SCCR2 has been set to 1. The HALT/STANDBY bit in SCCR2 controls the low-power mode selection.

In the STANDBY mode (HALT/STANDBY = 0), all CPU activity and most peripheral module activity stops; however, the oscillator, internal clocks, timer 1, and the receive-start bit detection circuit of the serial communications interface 2 remain active. System processing is suspended until a qualified interrupt (hardware $\overline{\text{RESET}}$, external interrupt on INT1, timer 1 interrupt, or low level in the receive pin of the SCI2) is detected.

In the HALT mode (HALT/STANDBY = 1), the TMS370CxCx is placed in its lowest power-consumption mode. The oscillator and internal clocks are stopped, causing all internal activity to be halted. System activity is suspended until a qualified interrupt (hardware $\overline{\text{RESET}}$, external interrupt on the INT1, or low level on the receive pin of the serial communications interface 2) is detected. The power-down mode selection bits are summarized in Table 9.

low-power and IDLE modes (continued)

Table 9. Low-Power/Idle Control Bits

POWER-DOWN CONTROL BITS		MODE SELECTED
PWRDWN/IDLE (SCCR2.6)	HALT/STANDBY (SCCR2.7)	
1	0	STANDBY
1	1	HALT
0	X †	IDLE

† Don't care

When low-power modes are disabled through a programmable contact in the mask-ROM devices, writing to the SCCR2.6-7 bits are ignored. In addition, if an idle instruction executes when low-power modes are disabled through a programmable contact, the device always enters the IDLE mode.

To provide a method of always exiting low-power modes for mask-ROM devices, INT1 is enabled automatically as a nonmaskable interrupt (NMI) during low-power modes when the hard watchdog mode is selected. This means that the NMI always is generated, regardless of the interrupt enable flags.

The following information is preserved throughout both the STANDBY and HALT modes: RAM (register file), CPU registers (stack pointer, program counter, and status register), I/O pin direction and output data, and status registers of all on-chip peripheral functions. Since all CPU instruction processing stops during the STANDBY and HALT modes, the clocking of the watchdog timer is inhibited.

clock modules

The 'xCx family provides two clock options that are referred to as divide-by-1 (phase-locked loop) and divide-by-4 (standard oscillator). Both the divide-by-1 and divide-by-4 options are configurable during the manufacturing process of a TMS370 microcontroller. The 'xCx ROM-masked devices offer both options to meet system engineering requirements. Only one of the two clock options is allowed on each ROM device. The '6C2A EPROM has only the divide-by-4.

The divide-by-1 clock module option provides the capability for reduced electromagnetic interference (EMI) with no added cost.

The divide-by-1 clock module option provides a one-to-one match of the external resonator frequency (CLKIN) to the internal system clock (SYSCLK) frequency, whereas the divide-by-4 option produces a SYSCLK which is one-fourth of the frequency of the external resonator. Inside of the divide-by-1 module, the frequency of the external resonator is multiplied by four, and the clock module then divides the resulting signal by four to provide the four-phased internal system clock signals. The resulting SYSCLK is equal to the resonator frequency.

clock modules (continued)

These are formulated as follows:

$$\text{Divide-by-4 : SYSCLK} = \frac{\text{external resonator frequency}}{4} = \frac{\text{CLKIN}}{4}$$

$$\text{Divide-by-1 : SYSCLK} = \frac{\text{external resonator frequency} \times 4}{4} = \text{CLKIN}$$

The main advantage of choosing a divide-by-1 oscillator is to reduce EMI. The harmonics of low-speed resonators extend through less of the emissions spectrum than the harmonics of faster resonators. The divide-by-1 option provides the capability of reducing the resonator speed by four times, resulting in a steeper decay of emissions produced by the oscillator.

system configuration registers

Table 10 contains system configuration and control functions. The privileged bits are shown in bold typeface and shaded areas.

Table 10. System Configuration Registers

PF	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
P010	COLD START	**OSC POWER**	**PF AUTO WAIT**	OSC FLT FLAG	MC PIN WPO	MC PIN DATA	—	µP/µC MODE	SCCR0
P011	—	—	—	**AUTO WAIT DISABLE**	—	**MEMORY DISABLE**	—	—	SCCR1
P012	**HALT/ STANDBY**	**PWRDWN/ IDLE**	—	**BUS STEST**	**CPU STEST**	—	**INT1 NMI**	**PRIVILEGE DISABLE**	SCCR2
P013 to P016	RESERVED								
P017	INT1 FLAG	INT1 PIN DATA	—	—	—	INT1 POLARITY	INT1 PRIORITY	INT1 ENABLE	INT1
P018 to P01B	RESERVED								
P01C	BUSY	VPPS	—	—	—	—	W0	EXE	EPCTL
P01D P01E P01F	RESERVED								

digital I/O port configuration registers

Peripheral file frame 2 contains the digital I/O pin configuration and control registers. Table 11 shows the specific addresses, registers, and control bits within this peripheral file frame. Table 12 shows the port-configuration register setup.

Table 11. Peripheral File Frame 2: Digital Port-Control Registers

PF	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	
P020	Reserved								APORT1
P021	Port A Control Register 2 (must be 0)								APORT2
P022	Port A Data								ADATA
P023	Port A Direction								ADIR
P024 to P02B	Reserved								
P02C	Port D Control Register 1 (must be 0)		—	Port D Control Register 1 (must be 0)		—	—	—	DPORT1
P02D	Port D Control Register 2 (must be 0)†		—	Port D Control Register 2 (must be 0)†		—	—	—	DPORT2
P02E	Port D Data		—	Port D Data		—	—	—	DDATA
P02F	Port D Direction		—	Port D Direction		—	—	—	DDIR

† To configure pin D3 as SYSCLK, set port D control register 2 = 08h.

Table 12. Port Configuration Register Set-up

PORT	PIN	abcd 00q1	abcd 00y0
A	0 – 7	Data Out q	Data In y
D	3, 4, 6, 7	Data Out q	Data In y
a = Port x Control Register 1 b = Port x Control Register 2 c = Data d = Direction			

programmable timer 1

The programmable Timer 1 (T1) module of the TMS370CxCx provides the designer with the enhanced timer resources required to perform real-time system control. The T1 module contains the general-purpose timer and the watchdog (WD) timer. The two independent 16-bit timers allow program selection of input clock sources (real-time, external event, or pulse accumulate) with multiple 16-bit registers (input capture and compare) for special timer function control. The T1 module includes three external device pins that can be used for multiple counter functions (operation mode dependent) or used as general-purpose I/O pins. The T1 module is shown in Figure 5.

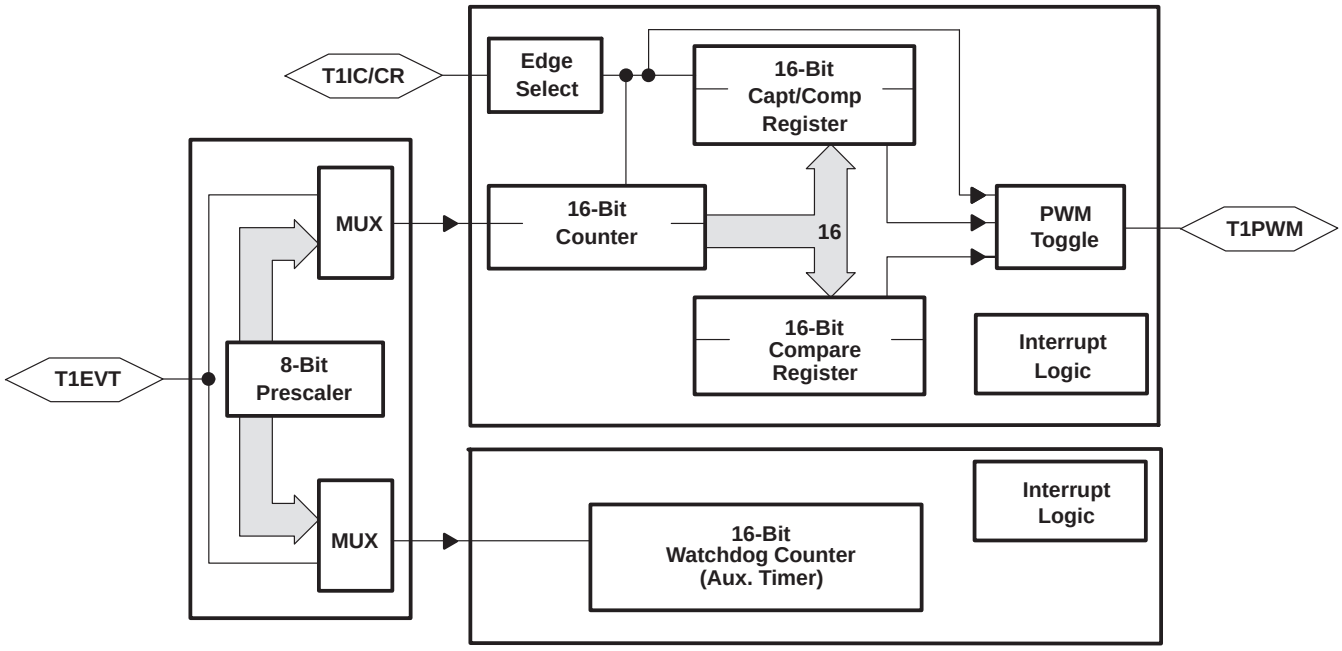


Figure 5. Timer 1 Block Diagram

- Three T1 I/O pins
  - T1IC/CR: Timer 1 input capture / counter reset input pin, or general-purpose bidirectional I/O pin
  - T1PWM: Timer 1 pulse-width-modulation (PWM) output pin, or general-purpose bidirectional I/O pin
  - T1EVT: Timer 1 event input pin, or general-purpose bidirectional I/O pin
- Two operation modes:
  - Dual-compare mode: Provides PWM signal
  - Capture/compare mode: Provides input capture pin
- One 16-bit general-purpose resettable counter
- One 16-bit compare register with associated compare logic
- One 16-bit capture/compare register, which, depending on the mode of operation, operates as either a capture or compare register.
- One 16-bit watchdog counter can be used as an event counter, a pulse accumulator, or an interval timer if watchdog feature is not needed.
- Prescaler/clock sources that determine one of eight clock sources for general-purpose timer

programmable timer 1 (continued)

- Selectable edge-detection circuitry that, depending on the mode of operation, senses active transitions on the input capture pins (T1IC/CR)
- Interrupts that can be generated on the occurrence of:
  - A capture
  - A compare equal
  - A counter overflow
  - An external edge detection
- Sixteen T1 module control registers located in the PF frame beginning at address P040.

programmable timer 1 (continued)

The T1 module control registers are listed in Table 13. Privilege bits are shown in bold typeface and shaded.

Table 13. Timer Module Register Memory Map

PF	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
	Mode: Dual-Compare and Capture/Compare								
P040	Bit 15			T1Counter MSbyte				Bit 8	T1CNTR
P041	Bit 7			T1 Counter LSbyte				Bit 0	
P042	Bit 15			Compare Register MSbyte				Bit 8	T1C
P043	Bit 7			Compare Register LSbyte				Bit 0	
P044	Bit 15			Capture/Compare Register MSbyte				Bit 8	T1CC
P045	Bit 7			Capture/Compare Register LSbyte				Bit 0	
P046	Bit 15			Watchdog Counter MSbyte				Bit 8	WDCNTR
P047	Bit 7			Watchdog Counter LSbyte				Bit 0	
P048	Bit 7			Watchdog Reset Key				Bit 0	WDRST
P049	WD OVRFL TAP SEL†	WD INPUT SELECT2†	WD INPUT SELECT1†	WD INPUT SELECT0†	—	T1 INPUT SELECT2	T1 INPUT SELECT1	T1 INPUT SELECT0	T1CTL1
P04A	WD OVRFL RST ENA†	WD OVRFL INT ENA	WD OVRFL INT FLAG	T1 OVRFL INT ENA	T1 OVRFL INT FLAG	—	—	T1 SW RESET	T1CTL2
	Mode: Dual-Compare								
P04B	T1EDGE INT FLAG	T1C2 INT FLAG	T1C1 INT FLAG	—	—	T1EDGE INT ENA	T1C2 INT ENA	T1C1 INT ENA	T1CTL3
P04C	T1 MODE=0	T1C1 OUT ENA	T1C2 OUT ENA	T1C1 RST ENA	T1CR OUT ENA	T1EDGE POLARITY	T1CR RST ENA	T1EDGE DET ENA	T1CTL4
	Mode: Capture / Compare								
P04B	T1EDGE INT FLAG	—	T1C1 INT FLAG	—	—	T1EDGE INT ENA	—	T1C1 INT ENA	T1CTL3
P04C	T1 MODE = 1	T1C1 OUT ENA	—	T1C1 RST ENA	—	T1EDGE POLARITY	—	T1EDGE DET ENA	T1CTL4
	Mode: Dual-Compare and Capture/Compare								
P04D	—	—	—	—	T1EVT DATA IN	T1EVT DATA OUT	T1EVT FUNCTION	T1EVT DATA DIR	T1PC1
P04E	T1PWM DATA IN	T1PWM DATA OUT	T1PWM FUNCTION	T1PWM DATA DIR	T1IC/CR DATA IN	T1IC/CR DATA OUT	T1IC/CR FUNCTION	T1IC/CR DATA DIR	T1PC2
P04F	**T1 STEST**	**T1 PRIORITY**	—	—	—	—	—	—	T1PRI

† Once the WD OVRFL RST ENA bit is set, these bits cannot be changed until a reset; this applies only to the standard watchdog and to simple counter. In the hard watchdog, these bits can be modified at any time; the WD INPUT SELECT2 bits are ignored.

programmable timer 1 (continued)

Figure 6 shows the T1 capture/compare mode block diagram. The annotations on the diagram identify the register and the bit(s) in the peripheral frame. For example, the actual address of T1CTL2.0 is 104Ah, bit 0, in the T1CTL2 register**.**

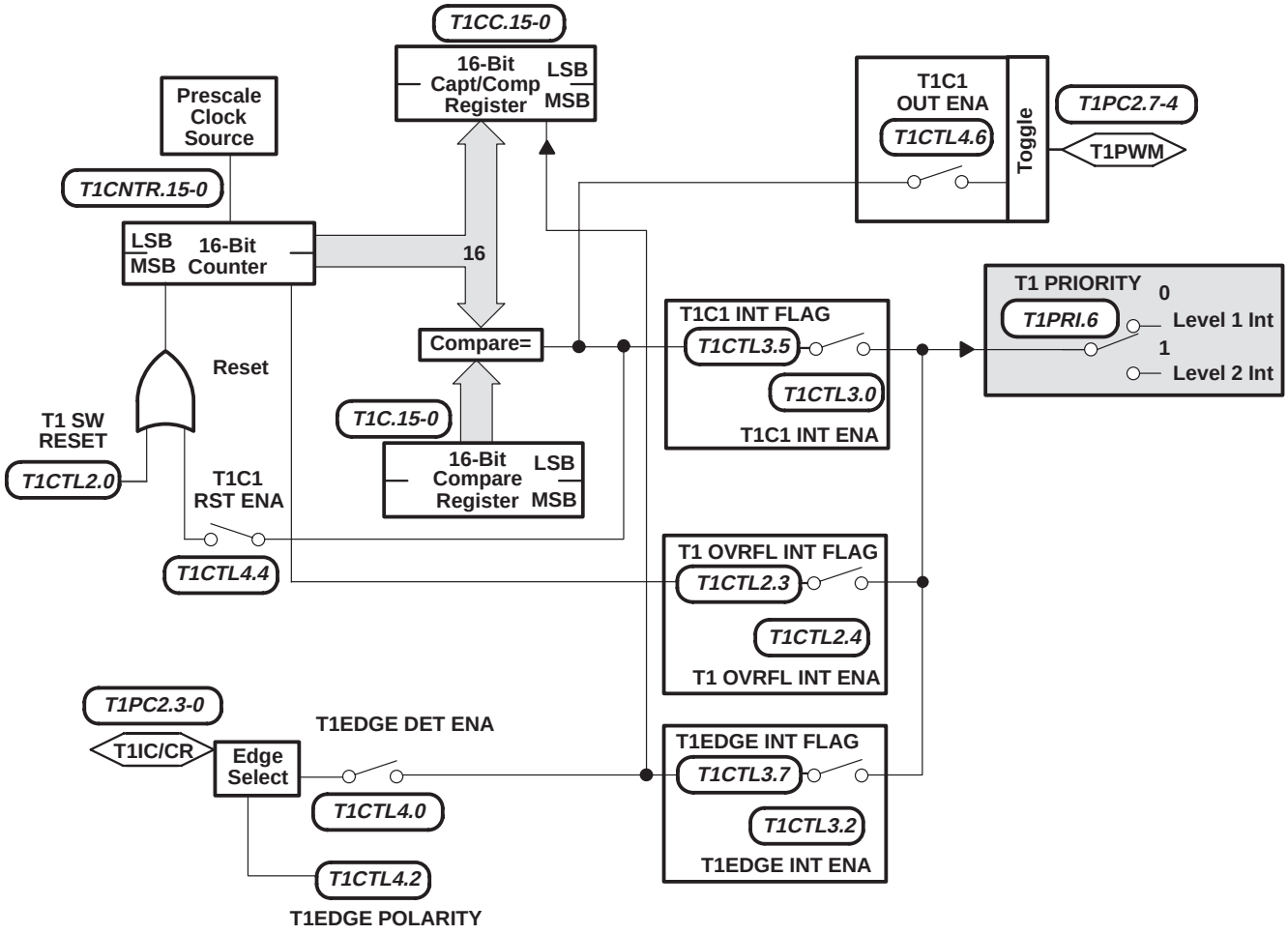


Figure 6. Capture/Compare Mode

programmable timer 1 (continued)

Figure 7 shows the T1 dual-compare mode block diagram. The annotations on the diagram identify the register and the bit(s) in the peripheral frame. For example, the actual address of T1CTL2.0 is 104Ah, bit 0, in the T1CTL2 register.

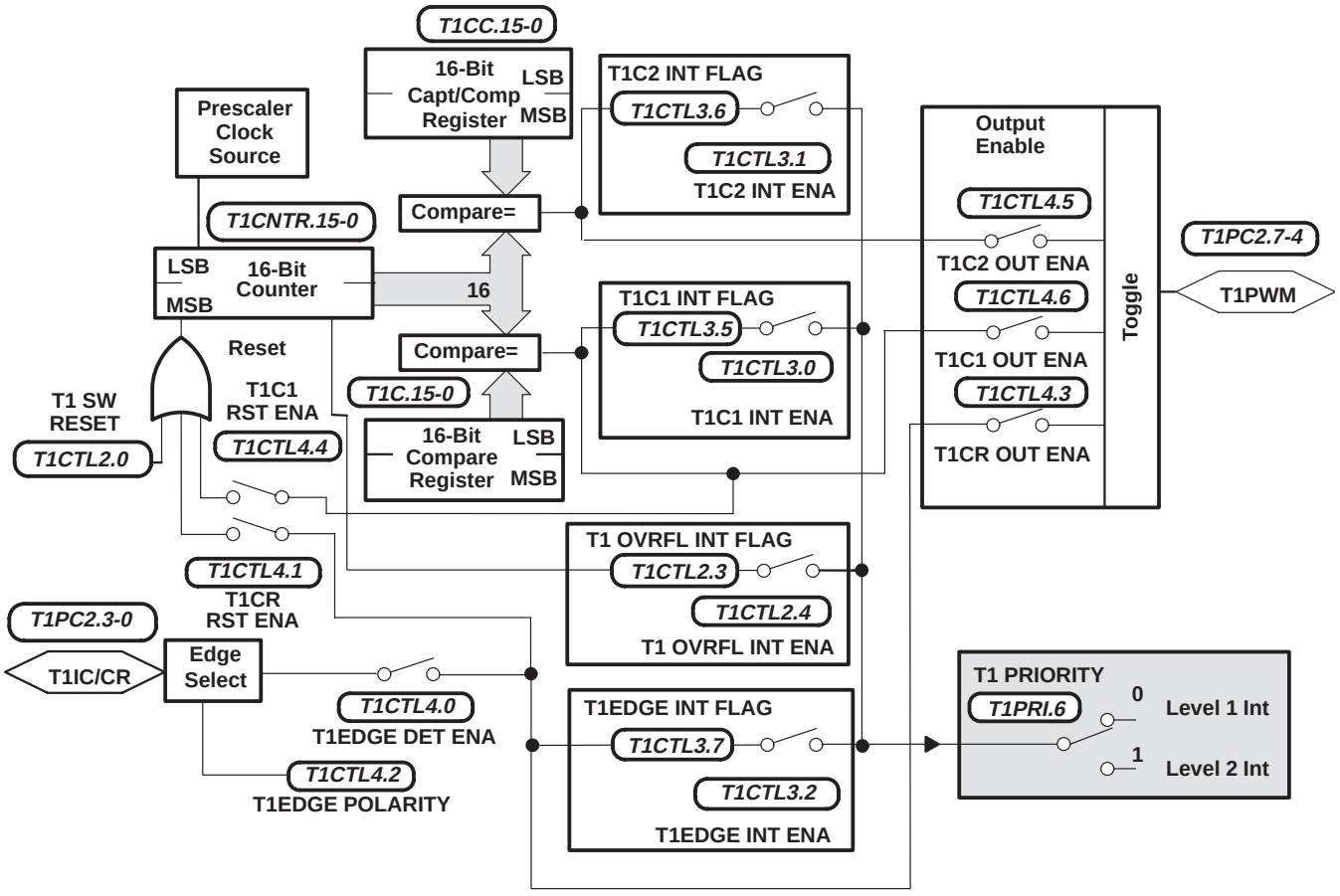


Figure 7. Dual-Compare Mode

programmable timer 1 (continued)

The TMS370CxCx device includes a 24-bit WD timer, contained in the T1 module, which can be programmed as an event counter, pulse accumulator, or interval timer if the watchdog function is not used. The WD function is to monitor software and hardware operation and to implement a system reset when the WD counter is not properly serviced (WD counter overflow or WD counter is re-initialized by an incorrect value). The WD can be configured as one of the three mask options as follows:

- Standard watchdog configuration (see Figure 8) – for EPROM and mask-ROM devices:
  - Watchdog mode
    - Ten different WD overflow rates ranging from 6.55 ms to 3.35 s at 5 MHz SYSCLK
    - A WD reset key (WDRST) register is used to clear the watchdog counter (WDCNTR) when a correct value is written.
    - Generates a system reset if an incorrect value is written to the watchdog reset key or if the counter overflows
    - A watchdog overflow flag (WD OVRFL INT FLAG) bit that indicates whether the WD timer initiated a system reset
  - Non-watchdog mode
    - Watchdog timer can be configured as an event counter, pulse accumulator, or an interval timer.

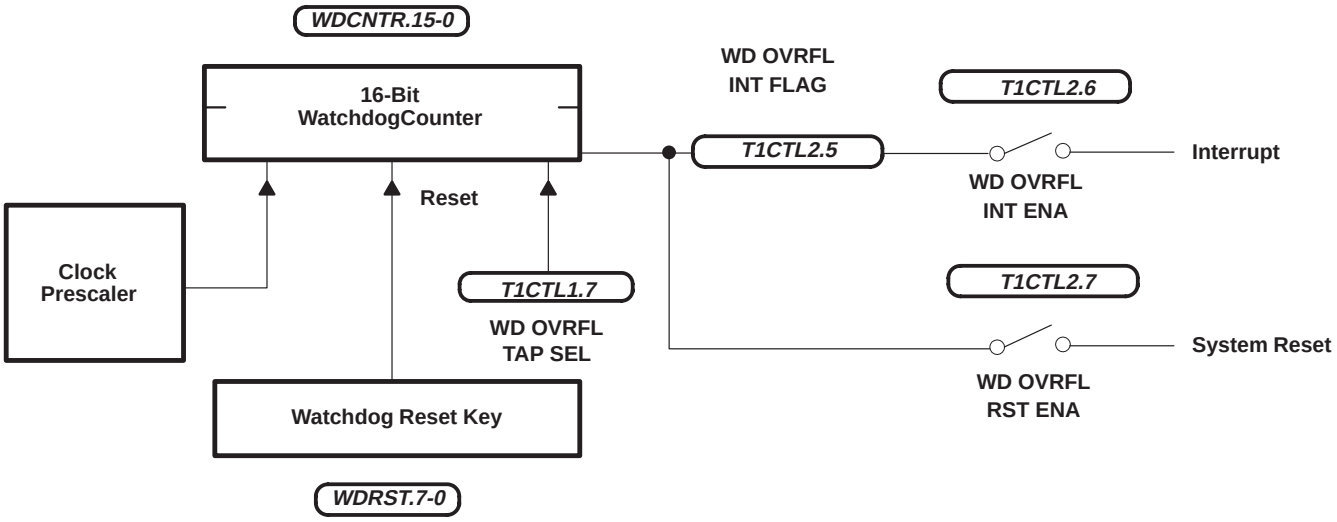


Figure 8. Standard Watchdog

programmable timer 1 (continued)

- Hard watchdog configuration (see Figure 9) – for mask-ROM devices:
  - Eight different WD overflow rates ranging from 26.2 ms to 3.35 s at 5 MHz SYSCLK
  - A WD reset key (WDRST) register is used to clear the watchdog counter (WDCNTR) when a correct value is written.
  - Generates a system reset if an incorrect value is written to the watchdog reset key or if the counter overflows.
  - Automatic activation of the WD timer upon power-up reset
  - INT1 is enabled as a nonmaskable interrupt during low-power modes.
  - A watchdog overflow flag (WD OVRFL INT FLAG) bit that indicates whether the WD timer initiated a system reset

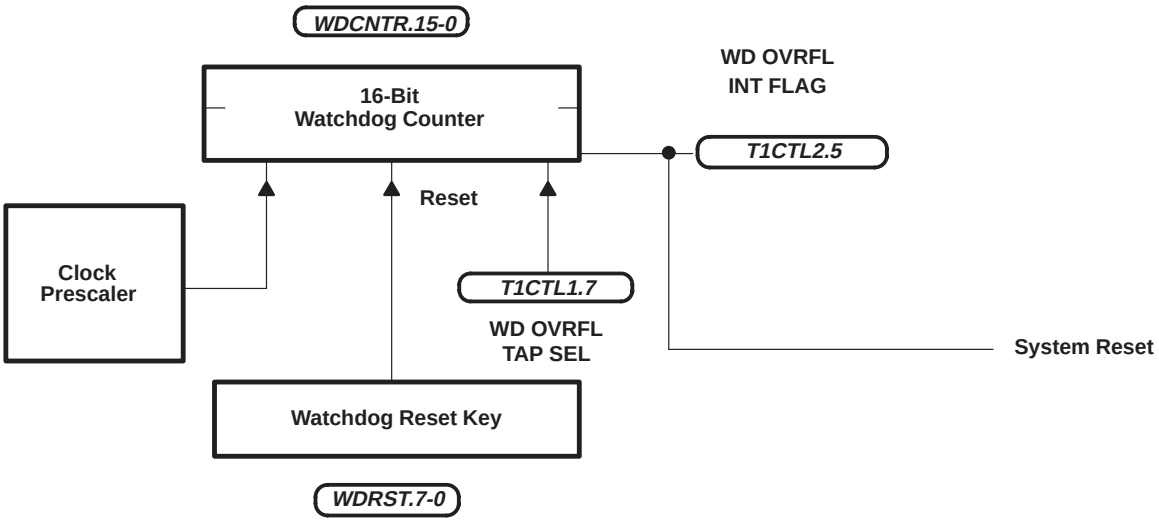


Figure 9. Hard Watchdog

- Simple counter configuration – for mask-ROM devices only (see Figure 10)
  - Simple counter can be configured as an event counter, pulse accumulator, or an internal timer.

programmable timer 1 (continued)

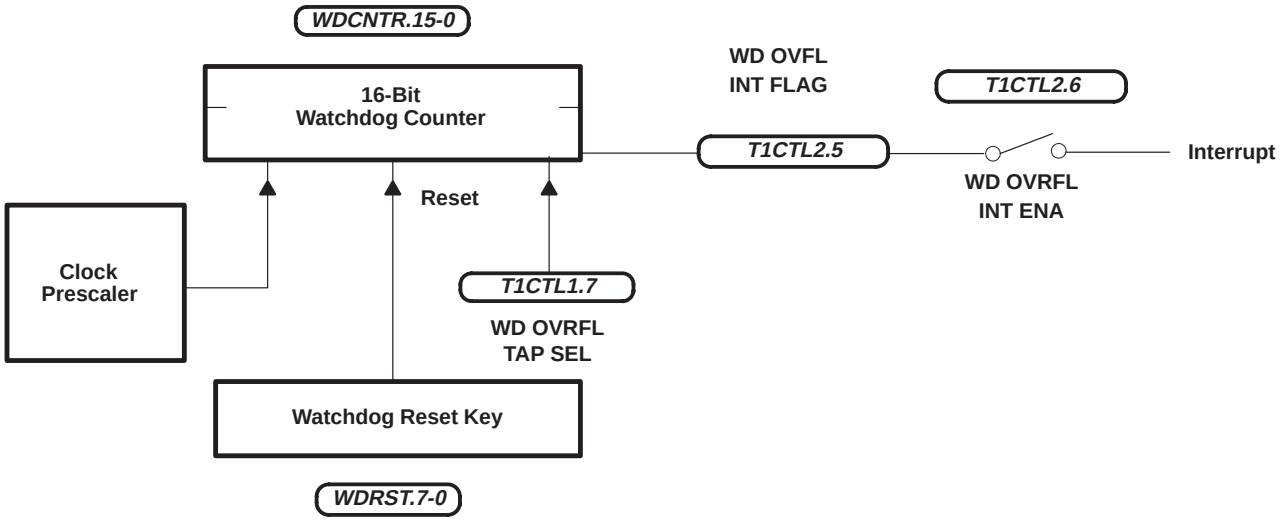


Figure 10. Simple Counter

serial communications interface 2 module

The TMS370CxCx devices include a serial communications interface 2 (SCI2) module. The SCI2 module supports digital communications between the TMS370 devices and other asynchronous peripherals and uses the standard non-return-zero (NRZ) format. The SCI2 modules receiver and transmitter are double buffered, and each has its own separate enable and interrupt bits. Both can be operated independently or simultaneously in the full duplex mode. To ensure data integrity, the SCI2 checks received data for break detection, parity, overrun, and framing errors. The speed of bit rate (baud) is programmable to over 65,000 different speeds through a 16-bit baud-select register. Features of the SCI2 module include:

- Two external pins:
  - SCITXD: SCI2 module transmit-output pin or general-purpose bidirectional I/O pin.
  - SCIRXD: SCI2 module receive-input pin or general-purpose bidirectional I/O pin.
- Asynchronous communications mode
- Baud rate: 64K different programmable rates
  - Asynchronous mode: 3 bps to 156K bps at 5 MHz SYSCLK

$$\text{Asynchronous Baud} = \frac{\text{SYSCLK}}{(\text{BAUD REG} + 1) \times 32}$$

- Data word format:
  - One start bit
  - Data word length programmable from one to eight bits
  - Optional even/odd/no parity bit
  - One or two stop bits

serial communications interface 2 module (continued)

- Four error-detection flags: parity, overrun, framing, and break detection
- Two wake-up multiprocessor modes: Idle-line and address bit
- Half or full-duplex operation
- Double-buffered receiver and transmitter operations
- Transmitter and receiver operations can be accomplished through either interrupt-driven or polled-algorithms with status flags:
  - Transmitter: TXRDY flag (transmitter buffer register is ready to receive another character) and TX EMPTY flag (Transmitter shift register is empty)
  - Receiver: RXRDY flag (receive buffer register ready to receive another character), BRKDT flag (break condition occurred), and RX ERROR monitoring four interrupt conditions
  - Separate enable bits for transmitter and receiver interrupts
  - NRZ format
- Ten SCI2 module control registers located in control register frame beginning at address P050

The SCI2 module control registers are listed in Table 14. Privilege bits are shown in bold typeface and shaded.

Table 14. SCI2 Module Control Register Memory Map

PF	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
P050	STOP BITS	EVEN/ODD PARITY	PARITY ENABLE	ASYNC ENABLE	ADDRESS/ IDLE WUP	SCI CHAR2	SCI CHAR1	SCI CHAR0	SCICCR
P051	—	—	SCI SW RESET	CLOCK ENABLE	TXWAKE	SLEEP	TXENA	RXENA	SCICTL
P052	BAUDF (MSB)	BAUDE	BAUDD	BAUDC	BAUDB	BAUDA	BAUD9	BAUD8	BAUD MSB
P053	BAUD7	BAUD6	BAUD5	BAUD4	BAUD3	BAUD2	BAUD1	BAUD0 (LSB)	BAUD LSB
P054	TXRDY	TX EMPTY	—	—	—	—	—	SCI TX INT ENA	TXCTL
P055	RX ERROR	RXRDY	BRKDT	FE	OE	PE	RXWAKE	SCI RX INT ENA	RXCTL
P056	RESERVED								
P057	RXDT7	RXDT6	RXDT5	RXDT4	RXDT3	RXDT2	RXDT1	RXDT0	RXBUF
P058	RESERVED								
P059	TXDT7	TXDT6	TXDT5	TXDT4	TXDT3	TXDT2	TXDT1	TXDT0	TXBUF
P05A to P05D	RESERVED								
P05E	SCITXD DATA IN	SCITXD DATA OUT	SCITXD FUNCTION	SCITXD DATA DIR	SCIRXD DATA IN	SCIRXD DATA OUT	SCIRXD FUNCTION	SCIRXD DATA DIR	SCIPC2
P05F	**SCI STEST**	**SCITX PRIORITY**	**SCIRX PRIORITY**	**SCI ESPEN**	—	—	—	—	SCIPRI

serial communications interface 2 module (continued)

The SCI2 module block diagram is illustrated in Figure 11.

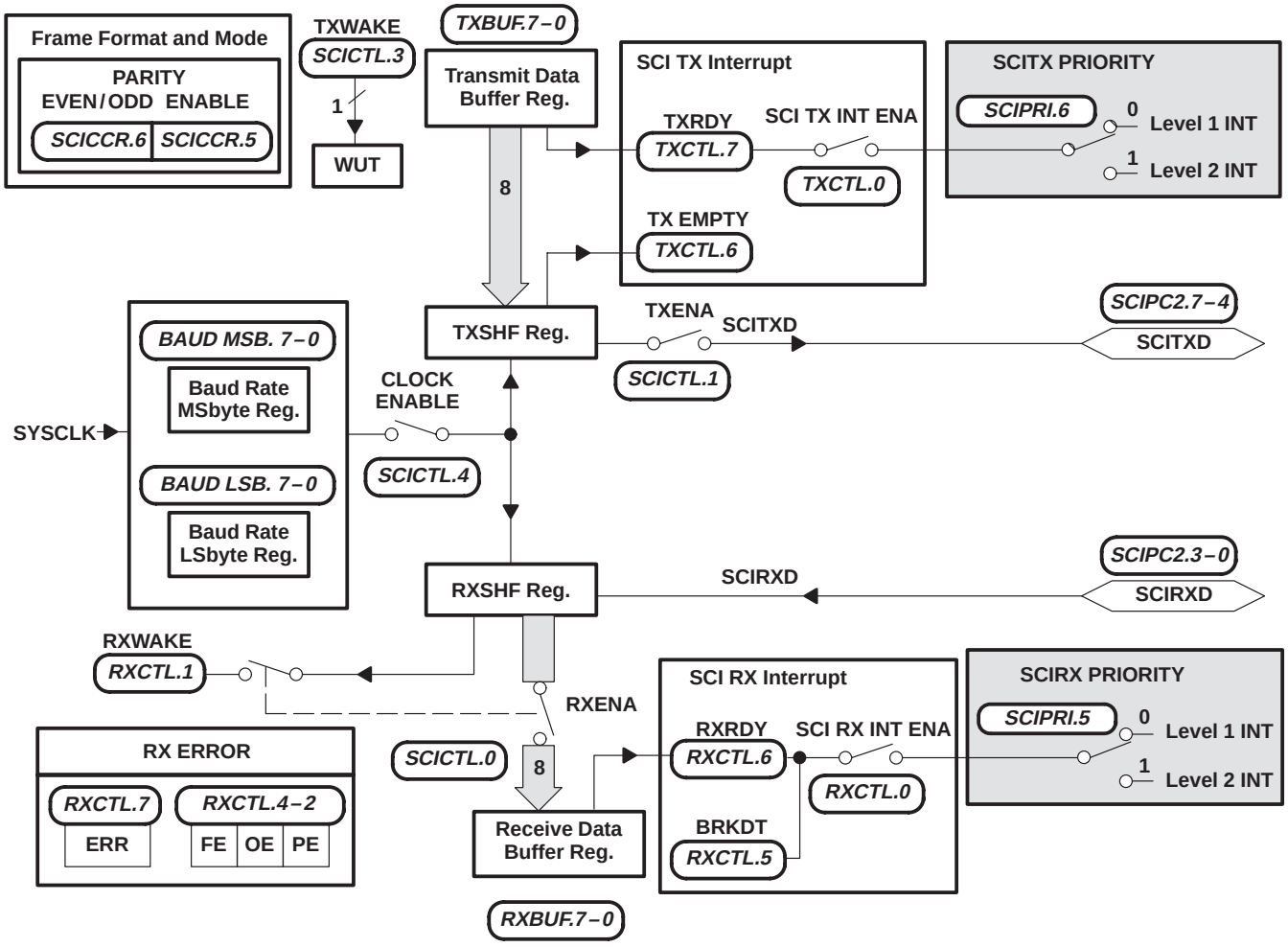


Figure 11. SCI2 Block Diagram

serial communications interface 2 module (continued)

SCI communication control register (SCICCR)

The SCICCR register defines the character format, protocol, and communications modes used by the SCI2.

Table 15. SCI Communication Control Register (SCICCR) [Memory Address – 1050h]

Bit #	7	6	5	4	3	2	1	0
P050	STOP BITS	EVEN/ODD PARITY	PARITY ENABLE	ASYNC ENABLE	ADDRESS/ IDLE WUP	SCI CHAR2	SCI CHAR1	SCI CHAR0
	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0

R = read, W = write, –*n* = value of the bit after the register is reset

Bits 0–2 SCI CHAR0–2 (SCI character length control bits 0–2)

These bits select the SCI character (data) bit length, from 1 to 8 bits. Characters of less than 8 bits are right-justified in RXBUF and TXBUF, and are padded with leading 0s in RXBUF. TXBUF need not be padded with leading 0s.

Table 16. Character Bit Length

SCI CHAR2	SCI CHAR1	SCI CHAR0	Character Length
0	0	0	1
0	0	1	2
0	1	0	3
0	1	1	4
1	0	0	5
1	0	1	6
1	1	0	7
1	1	1	8

Bit 3 ADDRESS/IDLE WUP (SCI multiprocessor mode control bit)

This bit selects the multiprocessor mode.

0 = Selects idle line mode

1 = Selects address bit mode

The idle line mode is usually used for normal communications because the address bit mode adds an extra bit to the frame; the idle line mode does not add this extra bit and is compatible with RS-232-type communications. Multiprocessor communication is different from the other communications modes because it uses TXWAKE and SLEEP functions.

Bit 4 ASYNC ENABLE (SCI asynchronous mode enable)

This bit enables or disables the asynchronous mode function. For SCI operation, this bit must be written as a 1 when writing to the SCICCR register.

0 = Disables asynchronous mode (SCI does not operate).

1 = Enables asynchronous mode (SCI operates).

serial communications interface 2 module (continued)

Bit 5 PARITY ENABLE (SCI parity enable)

This bit enables or disables the parity function. When parity is enabled during the address bit multiprocessor mode, the address bit is included in the parity calculation.

0 = Disables parity. No parity bit is generated during transmission or expected during reception.

1 = Enables parity

Bit 6 EVEN/ODD PARITY (SCI parity enable)

If the PARITY ENABLE bit is set, this bit selects odd or even parity (odd or even number of bits in both transmitted and received characters).

0 = Sets odd parity

1 = Sets even parity

Bit 7 STOP BITS (SCI number of stop bits)

This bit determines the number of stop bits transmitted. The receiver checks for one stop bit only.

0 = One stop bit

1 = Two stop bits

SCI control register (SCICTL)

The SCICTL register controls the RX/TX enable, TXWAKE and SLEEP functions, and the SCI software reset.

Table 17. SCI Control Register (SCICTL) [Memory Address – 1051h]

Bit #	7	6	5	4	3	2	1	0
P051	—	—	SCI SW RESET	CLOCK ENABLE	TXWAKE	SLEEP	TXENA	RXENA
			RW–0	RW–0	RS–0	RW–0	RW–0	RW–0

R = read, W = write, S = set only, –*n* = value of the bit after the register is reset

Bit 0 RXENA (SCI receive enable)

When this bit is set, received characters are transferred into RXBUF, and the RXRDY flag is set. When cleared, this bit prevents received characters from being transferred into the receiver buffer (RXBUF), and no receiver interrupts are generated. However, the receiver shift register continues to assemble characters. As a result, if RXENA is set during the reception of a character, the complete character is transferred into RXBUF.

0 = Disables SCI receiver

1 = Enables SCI receiver

Bit 1 TXENA (SCI transmit enable)

Data transmission through the SCITXD pin occurs only when this bit is set. If this bit is reset, the transmission is not halted until all the data previously written to TXBUF has been sent.

0 = Disables SCI transmitter

1 = Enables SCI transmitter

serial communications interface 2 module (continued)

Bit 2 SLEEP (SCI sleep)

This bit controls the receive features of the multiprocessor communication modes. This bit must be cleared to bring the SCI out of sleep mode.

0 = Disables sleep mode

1 = Enables sleep mode

Bit 3 TXWAKE (SCI transmitter wake-up)

The TXWAKE bit controls the transmit features of the multiprocessor communication modes. This bit is cleared only by system reset. The SCI hardware clears this bit, once it has been transferred to wake-up temporary (WUT).

Bit 4 CLOCK ENABLE (SCI internal clock enable)

This bit enables or disables the SCI internal clock. For SCI operation, this bit must be written as a 1 when writing to the SCICTL register.

0 = Disables SCI internal clock (stops SCI operation)

1 = Enables SCI internal clock (SCI operates)

Bit 5 SCI SW RESET (SCI software reset—active low)

Writing a 0 to this bit initializes the SCI state machines and operation flags to the reset condition. All affected logic is held in the reset state until a 1 is written to the SCI SW RESET bit. After a system reset, you must re-enable the SCI by writing a 1 to this bit. This bit must be cleared after a receiver break detect.

SCI SW RESET affects the operating flags of the SCI. This bit does not affect the configuration bits, nor does it put in the reset values. The flags listed in Table 18 are set to the values shown when SCI SW RESET is cleared. The operating flags are frozen until the SCI SW RESET bit is set again.

Table 18. Flags Affected by SCI SW RESET

SCI FLAG	DESIGNATION	VALUE AFTER SCI SW RESET
TXRDY	TXCTL.7	1
TXEMPTY	TXCTL.6	1
RXWAKE	RXCTL.1	0
PE	RXCTL.2	0
OE	RXCTL.3	0
FE	RXCTL.4	0
BRKDT	RXCTL.5	0
RXRDY	RXCTL.6	0
RX ERROR	RXCTL.7	0

Bits 6, 7 Reserved (read data is indeterminate)

baud-select registers (BAUD MSB and BAUD LSB)

The BAUD MSB and BAUD LSB registers store the data required to generate the bit rate. The SCI2 uses the combined 16-bit value, BAUD REG, of the baud-select registers to set the internal SCI2 clock frequency.

- For asynchronous-mode communication, data is transmitted and received at the rate of one bit for each 16 internal SCICLK periods.

serial communications interface 2 module (continued)

The asynchronous bit rates are calculated as follows:

Asynchronous Baud = SYSCLK / [(BAUD REG + 1) 32]

Table 19. Baud-Select Register (BAUD MSB) [Memory Address – 1052h]

Bit #	7	6	5	4	3	2	1	0
P052	BAUDF (MSB)	BAUDE	BAUDD	BAUDC	BAUDB	BAUDA	BAUD9	BAUD8
	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0

R = read, W = write, –*n* = value of the bit after the register is reset

Table 20. Baud-Select Register (BAUD LSB) [Memory Address – 1053h]

Bit #	7	6	5	4	3	2	1	0
P053	BAUD7	BAUD6	BAUD5	BAUD4	BAUD3	BAUD2	BAUD1	BAUD0 (LSB)
	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0

R = read, W = write, –*n* = value of the bit after the register is reset

SCI transmitter interrupt control and status register (TXCTL)

The TXCTL register contains the transmitter interrupt-enable bit, the transmitter-ready flag, and the transmitter-empty flag. The status flags are updated each time a complete character is transmitted.

Table 21. SCI Transmitter Interrupt Control and Status Register (TXCTL) [Memory Address – 1054h]

Bit #	7	6	5	4	3	2	1	0
P054	TXRDY	TX EMPTY	—	—	—	—	—	SCI TX INT ENA
	R–1	R–1						RW–0

R = read, W = write, –*n* = value of the bit after the register is reset

Bit 0 SCI TX INT ENA (SCI transmitter ready interrupt enable)

This bit controls the ability of the TXRDY bit to request an interrupt but does not prevent the TXRDY bit from being set. The SCI TX INT ENA bit is set to 0 by a system reset.

0 = Disables SCI TXRDY interrupt

1 = Enables SCI TXRDY interrupt

Bits 1–5 Reserved (read data is indeterminate)

serial communications interface 2 module (continued)

Bit 6 TX EMPTY (SCI transmitter empty)

This bit indicates the status of the transmitter-shift register and the TXBUF register. TX EMPTY is set to 1 by an SCI SW RESET or by a system reset.

0 = The CPU has written data to the TXBUF register; the data has not been completely transmitted.

1 = TXBUF and TXSHF registers are empty.

Bit 7 TXRDY (SCI transmitter ready)

The TXRDY bit is set by the transmitter to indicate that TXBUF is ready to receive another character. The bit is automatically cleared when a character is loaded into TXBUF. This flag asserts a transmitter interrupt if the interrupt-enable bit SCI TX INT ENA (TXCTL.0) is set. TXRDY is a read-only flag. It is set to 1 by an SCI SW RESET or by a system reset.

0 = TXBUF is full.

1 = TXBUF is ready to receive a character.

SCI receiver interrupt control and status register (RXCTL)

The RXCTL register contains one interrupt-enable bit and seven receiver-status flags (two of which can generate interrupt requests). The status flags are updated each time a complete character is transferred to the RXBUF. They are cleared each time RXBUF is read.

Table 22. SCI Receiver Interrupt Control and Status Register (RXCTL) [Memory Address – 1055h]

Bit #	7	6	5	4	3	2	1	0
P055	RX ERROR	RXRDY	BRKDT	FE	OE	PE	RXWAKE	SCI RX INT ENA
	R–0	R–0	R–0	R–0	R–0	R–0	R–0	RW–0

R = read, W = write, –*n* = value of the bit after the register is reset

Bit 0 SCI RX INT ENA (SCI receiver interrupt enable)

The SCI RX INT ENA bit controls the ability of the RXRDY and the BRKDT bits to request an interrupt but does not prevent these flags from being set.

0 = Disables RXRDY/BRKDT interrupt

1 = Enables RXRDY/BRKDT interrupt

Bit 1 RXWAKE (receiver wake-up detect)

The SCI sets this bit when a receiver wake-up condition is detected. In the address bit multiprocessor mode, RXWAKE reflects the value of the address bit for the character contained in RXBUF. In the idle line multiprocessor mode, RXWAKE is set if an idle SCIRXD line is detected. RXWAKE is a read-only flag. It is cleared by transfer of the first byte after the address byte to RXBUF, by reading the address character in RXBUF, by an SCI SW RESET, or by a system reset.

Bit 2 PE (SCI parity error flag)

This flag bit is set when a character is received with a mismatch between the number of 1s and its parity bit. The parity checker includes the address bit in the calculation. If parity generation and detection are not enabled, the PE flag is disabled and read as 0. The PE bit is reset by an SCI SW RESET, by a system reset, or by reading RXBUF.

0 = No parity error or parity is disabled

1 = Parity error detected

serial communications interface 2 module (continued)

Bit 3 OE (SCI overrun error flag)

The SCI sets this bit when a character is transferred into RXBUF before the previous character has been read out. The previous character is overwritten and lost. The OE flag is reset by an SCI SW RESET, by a system reset, or by reading RXBUF.

0 = No overrun error detected

1 = Overrun error detected

Bit 4 FE (SCI framing error flag)

The SCI sets this bit when it does not find a stop bit that it expects. Only the first stop bit is checked. The missing stop bit indicates that synchronization with the start bit has been lost and that the character is incorrectly framed. It is reset by an SCI SW RESET, by a system reset, or by reading RXBUF.

0 = No framing error detected

1 = Framing error detected

Bit 5 BRKDT (SCI break detect flag)

The SCI sets this bit when a break condition occurs. A break condition occurs when the SCIRXD line remains continuously low for at least 10 bits, beginning after a missing first stop bit. The occurrence of a break causes a receiver interrupt to be generated if the SCI RX INT ENA bit is a 1, but it does not cause the receiver buffer to be loaded. A BRKDT interrupt can occur, even if the receiver SLEEP bit is set to 1.

BRKDT is cleared by an SCI SW RESET or by a system reset. It is not cleared by receipt of a character after the break is detected. In order to receive more characters, the SCI must be reset by toggling the SCI SW RESET bit or by a system reset.

Bit 6 RXRDY (SCI receiver ready)

The receiver sets this bit to indicate that RXBUF is ready with a new character and clears the bit when the character is read. A receiver interrupt is generated if the SCI RX INT ENA bit is a 1. RXRDY is reset by an SCI SW RESET or by a system reset.

Bit 7 RX ERROR (SCI receiver error flag)

The RX ERROR flag indicates that one of the error flags in the receiver status register is set. It is a logical OR of the parity, overrun, framing error, and break detect flags. The bit can be used for fast error condition checking during the interrupt service routine because a negative value of the status register indicates that an error condition has occurred. This error flag cannot be cleared directly but is cleared if no individual error flags are set. This bit is cleared by an SCI SW RESET, by a system reset, or by reading RXBUF.

serial communications interface 2 module (continued)

SCI receiver data buffer register (RXBUF)

The RXBUF register contains current data from the receiver shift register. RXBUF is cleared by a system reset.

Table 23. SCI Receiver Data Buffer Register (RXBUF) [Memory Address – 1057h]

Bit #	7	6	5	4	3	2	1	0
P057	RXDT7	RXDT6	RXDT5	RXDT4	RXDT3	RXDT2	RXDT1	RXDT0
	R–0	R–0	R–0	R–0	R–0	R–0	R–0	R–0

R = read, W = write, –*n* = value of the bit after the register is reset

SCI transmitter data buffer register (TXBUF)

The TXBUF register is a read/write register that stores data bits to be transmitted by SCITX. Data written to TXBUF must be right-justified because the left-most bits are ignored for characters less than eight bits long.

Table 24. SCI Transmit Data Buffer Register (TXBUF) [Memory Address – 1059h]

Bit #	7	6	5	4	3	2	1	0
P059	TXDT7	TXDT6	TXDT5	TXDT4	TXDT3	TXDT2	TXDT1	TXDT0
	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0	RW–0

R = read, W = write, –*n* = value of the bit after the register is reset

SCI port control register 2 (SCIPC2)

The SCIPC2 register controls the SCIRXD and SCITXD pin functions.

Table 25. SCI Port Control Register 2 (SCIPC2) [Memory Address – 105Eh]

Bit #	7	6	5	4	3	2	1	0
P05E	SCITXD DATA IN	SCITXD DATA OUT	SCITXD FUNCTION	SCITXD DATA DIR	SCIRXD DATA IN	SCIRXD DATA OUT	SCIRXD FUNCTION	SCIRXD DATA DIR
	R–0	RW–0	RW–0	RW–0	R–0	RW–0	RW–0	RW–0

R = read, W = write, –*n* = value of the bit after the register is reset

Bit 0 SCIRXD DATA DIR (SCIRXD data direction)

This bit determines the data direction on the SCIRXD pin if SCIRXD has been defined as a general-purpose I/O pin.

0 = SCIRXD pin is a general-purpose input pin.

1 = SCIRXD pin is a general-purpose output pin.

Bit 1 SCIRXD FUNCTION

This bit defines the function of the SCIRXD pin.

0 = SCIRXD pin is a general-purpose digital I/O pin.

1 = SCIRXD pin is the SCI receiver pin.

serial communications interface 2 module (continued)

Bit 2 SCIRXD DATA OUT

This bit contains the data to be output on the SCIRXD pin if the following conditions are met:

- SCIRXD pin has been defined as a general-purpose I/O pin.
- SCIRXD pin data direction has been defined as output.

Bit 3 SCIRXD DATA IN

This bit contains the current value on the SCIRXD pin.

Bit 4 SCITXD DATA DIR (SCITXD data direction)

This bit determines the data direction on the SCITXD pin if SCITXD has been defined as a general-purpose I/O pin.

0 = SCITXD pin is a general-purpose input pin.

1 = SCITXD pin is a general-purpose output pin.

Bit 5 SCITXD FUNCTION

This bit defines the function of the SCITXD pin.

0 = SCITXD pin is a general-purpose digital I/O pin.

1 = SCITXD pin is the SCI transmit pin.

Bit 6 SCITXD DATA OUT

This bit contains the data to be output on the SCITXD pin if the following conditions are met:

- SCITXD pin has been defined as a general-purpose I/O pin.
- SCITXD pin data direction has been defined as output.

Bit 7 SCITXD DATA IN

This bit contains the current value on the SCITXD pin.

SCI priority control register (SCIPRI)

The SCIPRI register contains the receiver and transmitter interrupt-priority select bits. This register is read-only during normal operation but can be written to in the privileged mode.

Table 26. SCI Priority Control Register (SCIPRI) [Memory Address – 105Fh]

Bit #	7	6	5	4	3	2	1	0
P05F	SCI STEST	SCITX PRIORITY	SCIRX PRIORITY	SCI ESPEN	—	—	—	—
	RP–0	RP–0	RP–0	RP–0				

R = read, P = privilege write only, –*n* = value of the bit after the register is reset

Bits 0–3 Reserved (read data is indeterminate)

serial communications interface 2 module (continued)

Bit 4 SCI ESPEN (SCI emulator suspend enable)

This bit has no effect except when you are using the XDS emulator to debug a program. Then, this bit determines how the SCI operates when the program is suspended by an action such as a hardware or software breakpoint.

0 = When the emulator is suspended, the SCI continues to work until the current transmit or receive sequence is complete.

1 = When the emulator is suspended, the SCI state machine is frozen so that the state of the SCI can be examined at the point that the emulator was suspended.

Bit 5 SCI RX PRIORITY (SCI receiver interrupt priority select)

This bit assigns the interrupt-priority level of the SCI receiver interrupts.

0 = Receiver interrupts are level 1 (high-priority) requests.

1 = Receiver interrupts are level 2 (low-priority) requests.

Bit 6 SCI TX PRIORITY (SCI transmitter interrupt priority select)

This bit assigns the interrupt-priority level of the SCI transmitter interrupts.

0 = Transmitter interrupts are level 1 (high-priority) requests.

1 = Transmitter interrupts are level 2 (low-priority) requests.

Bit 7 SCI STEST (SCI STEST)

analog-to-digital converter 2 module

The analog-to-digital converter 2 (ADC2) module is an 8-bit, successive approximation converter with internal sample-and-hold circuitry. The module has four multiplexed analog input channels that allow the processor to convert the voltage levels from up to four different sources. The ADC2 module features include the following:

- Minimum conversion time: 32.8 μs at 5 MHz SYSCLK
- Four external pins:
  - Four analog input channels (AN0–AN3), any of which can be software configured as digital inputs (E0–E3) if not needed as analog channels
  - AN1–AN3 also can be configured as positive-input voltage reference.
- The ADDATA register, which contains the digital result of the last analog-to-digital (A/D) conversion
- A/D operations can be accomplished through either interrupt-driven or polled algorithms.
- Six ADC2 module control registers located in the control register frame beginning at address 1070h

analog-to-digital converter 2 module (continued)

The ADC2 module control registers are listed in Table 27.

Table 27. ADC2 Module Control Register Memory Map

PF	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
P070	CONVERT START	SAMPLE START	—	REF VOLT SELECT1	REF VOLT SELECT0	—	AD INPUT SELECT1	AD INPUT SELECT0	ADCTL
P071	—	—	—	—	—	AD READY	AD INT FLAG	AD INT ENA	ADSTAT
P072	A/D Conversion Data Register								ADDATA
P073 to P07C	RESERVED								
P07D	—	—	—	—	Port E Data Input Register				ADIN
P07E	—	—	—	—	Port E Input Enable Register				ADENA
P07F	**AD STEST**	**AD PRIORITY**	**AD ESPEN**	—	—	—	—	—	ADPRI

analog-to-digital converter 2 module (continued)

The ADC2 module block diagram is illustrated in Figure 12.

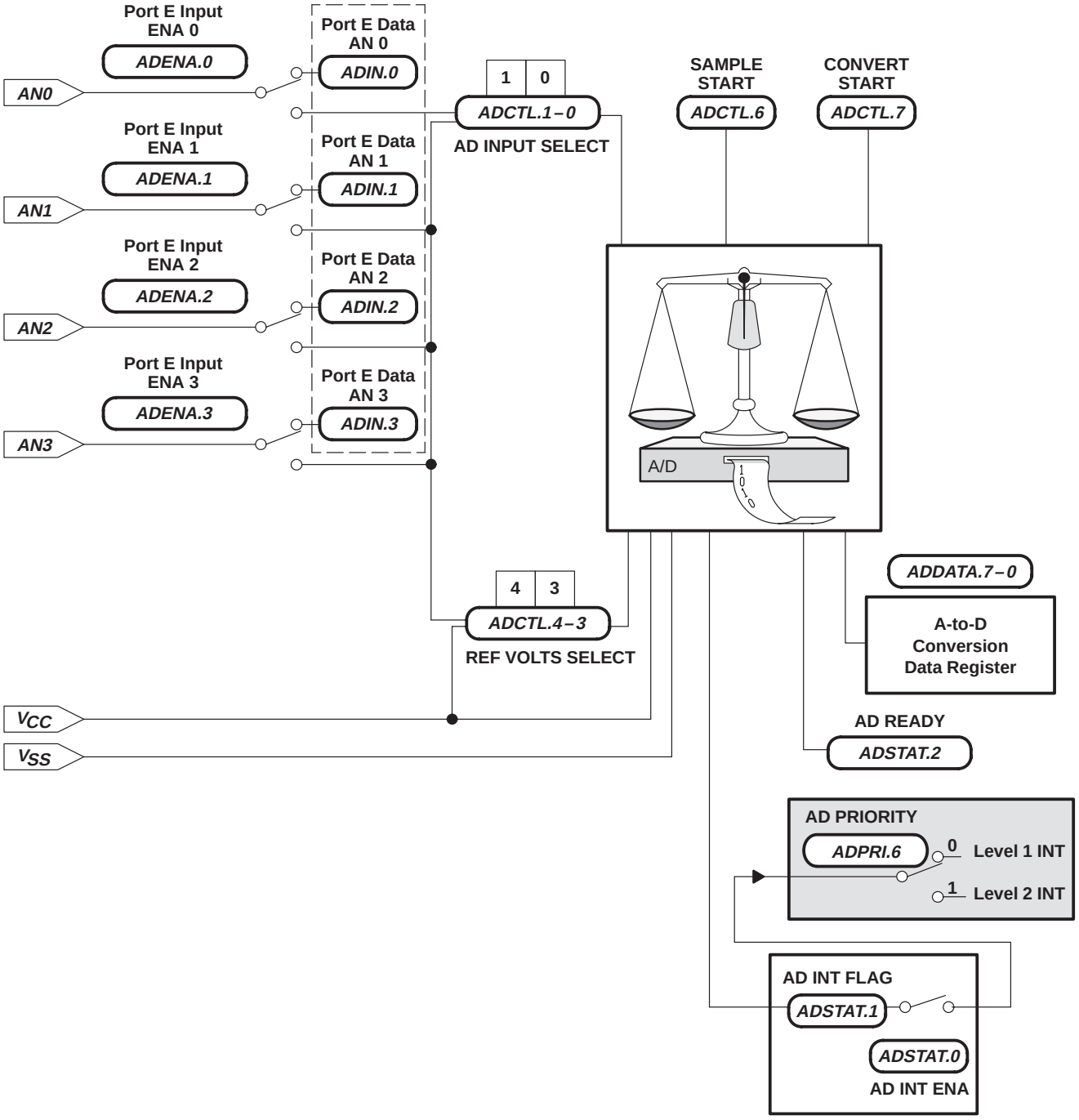


Figure 12. ADC2 Block Diagram

analog-to-digital converter 2 module (continued)

Table 28. A/D CONTROL REGISTER (ADCTL)

Bit #	7	6	5	4	3	2	1	0
P070	CONVERT START	SAMPLE START	—	REF VOLT SELECT1	REF VOLT SELECT0	—	AD INPUT SELECT1	AD INPUT SELECT0
	RW–0	RW–0		RW–0	RW–0	RW–0	RW–0	RW–0

R = read, W = write, –*n* = value of the bit after the register is reset

Bits 0–1 AD INPUT SELECT 0–1 (analog input channel select bits 0–1)

These bits select the channel used for conversion. Channels should be changed only after the ADC2 module has cleared the SAMPLE START and CONVERT START bits. Changing the channel while either SAMPLE START or CONVERT START is 1 invalidates the conversion in progress.

Table 29. Analog-Input Channel Selection

AD INPUT SELECT 1	AD INPUT SELECT 0	AD INPUT CHANNEL
0	0	AN0
0	1	AN1
1	0	AN2
1	1	AN3

Bit 2 Reserved (read data is indeterminate)

Bits 3–4 REF VOLT SELECT 3–4 (reference voltage ($+V_{REF}$) select bits 3–4)

These bits select the channel the ADC2 module uses for the positive voltage reference. These bits must not change during the entire conversion.

Table 30. Voltage-Channel Selection

REF VOLT SELECT 1	REF VOLT SELECT 0	$+V_{REF}$ SOURCE
0	0	V_{CC}
0	1	AN1
1	0	AN2
1	1	AN3

Bit 5 Reserved (read data is indeterminate)

Bit 6 SAMPLE START (sample start)

Setting this bit stops any ongoing conversion and starts sampling the selected input channel to begin a new conversion. This bit is cleared by the ADC2 module. Entering HALT or STANDBY mode clears this bit and aborts any sampling in progress.

Bit 7 CONVERT START (conversion start)

Setting this bit starts the conversion. This bit is cleared by the ADC2 module. Entering HALT or STANDBY mode clears this bit and aborts any conversion in progress.

analog-to-digital converter 2 module (continued)

Table 31. A/D Control Register (ADSTAT)

Bit #	7	6	5	4	3	2	1	0
P071	—	—	—	—	—	AD READY	AD INT FLAG	AD INT ENA
						R–0	RC–0	RW–0

R = read, W = write, C = clear only, –*n* = value of the bit after the register is reset

Bit 0 AD INT ENA (A/D interrupt enable)

This bit controls the ADC2 module's ability to generate an interrupt.

0 = Disable A/D interrupt

1 = Enable A/D interrupt

Bit 1 AD INT FLAG (A/D interrupt flag)

The ADC2 module sets this bit at the end of an ADC2 conversion. If this bit is set while the A/D INT ENA bit is set, an interrupt request is generated. Clearing this flag clears pending A/D interrupt requests. This bit is cleared by the system reset or by entering HALT or STANDBY mode. Software cannot set this bit.

Bit 2 AD READY (A/D converter ready)

The ADC2 module sets this bit whenever a conversion is not in progress and the ADC2 is ready for a new conversion to start. Writing to this bit has no effect on its state.

0 = Conversion is in process

1 = Converter is ready

Bits 3–7 Reserved (read data is indeterminate)

Table 32. A/D Conversion Data Register (DATA)

Bit #	7	6	5	4	3	2	1	0
P072	DATA 7	DATA 6	DATA 5	DATA 4	DATA 3	DATA 2	DATA 1	DATA 0
	R–0	R–0	R–0	R–0	R–0	R–0	R–0	R–0

R = read, –*n* = value of the bit after the register is reset

The analog-to-digital conversion data is loaded into this register at the end of a conversion and remains until replaced by another conversion.

Table 33. AN0–AN3 Port E0–E3 Data Input Register (ADIN)

Bit #	7	6	5	4	3	2	1	0
P07D	—	—	—	—	DATA IN AN3	DATA IN AN2	DATA IN AN1	DATA IN AN0
					R–0	R–0	R–0	R–0

R = read, –*n* = value of the bit after the register is reset

analog-to-digital converter 2 module (continued)

Bits 0–3 PORT E DATA AN0–AN3 (Analog port E data in)

The ADIN register shows the data present at the pins configured for general-purpose input instead of ADC2 channels. A bit is configured as general-purpose input if the corresponding bit of the port enable register is a 1. Pins configured as ADC2 channels are read as 0s. Writing to this address has no effect.

Bits 4–7 Reserved (read data is indeterminate)

Table 34. AN0 – AN3 Port E0 – E3 Data Input-Enable Register (ADENA)

Bit #	7	6	5	4	3	2	1	0
P07E	—	—	—	—	INPUT ENA 3	INPUT ENA 2	INPUT ENA 1	INPUT ENA 0
					RW – 0	RW – 0	RW – 0	RW – 0

R = read, W = write, *–n* = value of the bit after the register is reset

Bits 0–3 INPUT ENA 0–3 (Analog port E input enable)

The ADENA register individually configures the pins AN0–AN3 as either analog-input channels or as general-purpose input pins.

0 = The pin becomes an analog-input channel for the ADC2. When the bit is 0, the corresponding bit in the ADIN register reads 0.

1 = Enables the pin as a general-purpose input pin and its digital value can be read from the corresponding bit in the ADIN register.

Bits 4–7 Reserved (read data is indeterminate)

Table 35. Analog Interrupt Priority / Conversion Rate Register (ADPRI)

Bit #	7	6	5	4	3	2	1	0
P07F	AD STEST	AD PRIORITY	AD ESPEN	—	—	—	—	—
	RP – 0	RP – 0	RP – 0				RW – 0	RW – 0

R = read, W = write, P = privileged write, *–n* = value of the bit after the register is reset

Bits 0–4 Reserved (read data is indeterminate)

Bit 5 AD ESPEN (emulator suspend enable)

Normally this bit has no effect. However, when using the XDS emulator to debug a program, this bit determines what happens to the ADC2 when the program is suspended by an action such as a hardware or software breakpoint.

0 = When the emulator is suspended, the ADC2 continues to run until the conversion is complete

1 = When the emulator is suspended, the ADC2 is frozen so that its state can be examined at the point that the emulator was suspended. The conversion data is indeterminate upon restart.

analog-to-digital converter 2 module (continued)

Bit 6 AD PRIORITY (A/D interrupt priority select)

This bit selects the priority level of the A/D interrupt.

0 = A/D Interrupt is a higher priority (level 1) request.

1 = A/D Interrupt is a lower priority (level 2) request.

Bit 7 AD STEST (this bit must be cleared to ensure proper operation)

instruction set overview

Table 36 provides an opcode-to-instruction cross-reference of all 73 instructions and 274 opcodes of the ‘370CxCx instruction set. The numbers at the top of this table represent the most significant nibble of the opcode while the numbers at the left side of the table represent the least significant nibble. The instructions for these two opcode nibbles contain the mnemonic, operands, and byte/cycle specific to that opcode.

For example, the opcode B5h points to the CLR A instruction. This instruction contains one byte and executes in eight SYSCLK cycles.

Table 36. TMS370 Family Opcode/Instruction Map†

LSN \ MSN	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
0	JMP #ra 2/7							INCW #ra,Rd 3/11	MOV Ps,A 2/8			CLRC / TST A 1/9	MOV A,B 1/9	MOV A,Rd 2/7	TRAP 15 1/14	LDST n 2/6
1	JN ra 2/5		MOV A,Pd 2/8			MOV B,Pd 2/8		MOV Rs,Pd 3/10		MOV Ps,B 2/7				MOV B,Rd 2/7	TRAP 14 1/14	MOV #ra[SP],A 2/7
2	JZ ra 2/5	MOV Rs,A 2/7	MOV #n,A 2/6	MOV Rs,B 2/7	MOV Rs,Rd 3/9	MOV #n,B 2/6	MOV B,A 1/8	MOV #n,Rd 3/8			MOV Ps,Rd 3/10	DEC A 1/8	DEC B 1/8	DEC Rd 2/6	TRAP 13 1/14	MOV A,*ra[SP] 2/7
3	JC ra 2/5	AND Rs,A 2/7	AND #n,A 2/6	AND Rs,B 2/7	AND Rs,Rd 3/9	AND #n,B 2/6	AND B,A 1/8	AND #n,Rd 3/8	AND A,Pd 2/9	AND B,Pd 2/9	AND #n,Pd 3/10	INC A 1/8	INC B 1/8	INC Rd 2/6	TRAP 12 1/14	CMP *n[SP],A 2/8
4	JP ra 2/5	OR Rs,A 2/7	OR #n,A 2/6	OR Rs,B 2/7	OR Rs,Rd 3/9	OR #n,B 2/6	OR B,A 1/8	OR #n,Rd 3/8	OR A,Pd 2/9	OR B,Pd 2/9	OR #n,Pd 3/10	INV A 1/8	INV B 1/8	INV Rd 2/6	TRAP 11 1/14	extend inst,2 opcodes
5	JPZ ra 2/5	XOR Rs,A 2/7	XOR #n,A 2/6	XOR Rs,B 2/7	XOR Rs,Rd 3/9	XOR #n,B 2/6	XOR B,A 1/8	XOR #n,Rd 3/8	XOR A,Pd 2/9	XOR B,Pd 2/9	XOR #n,Pd 3/10	CLR A 1/8	CLR B 1/8	CLR Rn 2/6	TRAP 10 1/14	
6	JNZ ra 2/5	BTJO Rs,A,ra 3/9	BTJO #n,A,ra 3/8	BTJO Rs,B,ra 3/9	BTJO Rs,Rd,ra 4/11	BTJO #n,B,ra 3/8	BTJO B,A,ra 2/10	BTJO #n,Rd,ra 4/10	BTJO A,Pd,ra 3/11	BTJO B,Pd,ra 3/10	BTJO #n,Pd,ra 4/11	XCHB A 1/10	XCHB A / TST B 1/10	XCHB Rn 2/8	TRAP 9 1/14	IDLE 1/6
7	JNC ra 2/5	BTJZ Rs.,A,ra 3/9	BTJZ #n,A,ra 3/8	BTJZ Rs,B,ra 3/9	BTJZ Rs,Rd,ra 4/11	BTJZ #n,B,ra 3/8	BTJZ B,A,ra 2/10	BTJZ #n,Rd,ra 4/10	BTJZ A,Pd,ra 3/10	BTJZ B,Pd,ra 3/10	BTJZ #n,Pd,ra 4/11	SWAP A 1/11	SWAP B 1/11	SWAP Rn 2/9	TRAP 8 1/14	MOV #n,Pd 3/10
8	JV ra 2/5	ADD Rs,A 2/7	ADD #n,A 2/6	ADD Rs,B 2/7	ADD Rs,Rd 3/9	ADD #n,B 2/6	ADD B,A 1/8	ADD #n,Rd 3/8	MOVW #16,Rd 4/13	MOVW Rs,Rd 3/12	MOVW #16[B],Rpd 4/15	PUSH A 1/9	PUSH B 1/9	PUSH Rd 2/7	TRAP 7 1/14	SETC 1/7
9	JL ra 2/5	ADC Rs,A 2/7	ADC #n,A 2/6	ADC Rs,B 2/7	ADC Rs,Rd 3/9	ADC #n,B 2/6	ADC B,A 1/8	ADC #n,Rd 3/8	JMPL lab 3/9	JMPL *Rp 2/8	JMPL *lab[B] 3/11	POP A 1/9	POP B 1/9	POP Rd 2/7	TRAP 6 1/14	RTS 1/9
A	JLE ra 2/5	SUB Rs,A 2/7	SUB #n,A 2/6	SUB Rs,B 2/7	SUB Rs,Rd 3/9	SUB #n,B 2/6	SUB B,A 1/8	SUB #n,Rd 3/8	MOV & lab,A 3/10	MOV *Rp,A 2/9	MOV *lab[B],A 3/12	DJNZ A,#ra 2/10	DJNZ B,#ra 2/10	DJNZ Rd,#ra 3/8	TRAP 5 1/14	RTI 1/12
B	JHS ra 2/5	SBB Rs,A 2/7	SBB #n,A 2/6	SBB Rs,B 2/7	SBB Rs,Rd 3/9	SBB #n,B 2/6	SBB B,A 1/8	SBB #n,Rd 3/8	MOV A, & lab 3/10	MOV A, *Rp 2/9	MOV A,*lab[B] 3/12	COMPL A 1/8	COMPL B 1/8	COMPL Rd 2/6	TRAP 4 1/14	PUSH ST 1/8

† All conditional jumps (opcodes 01-0F), BTJO, BTJZ, and DJNZ instructions use two additional cycles if the branch is taken. The BTJO, BTJZ, and DJNZ instructions have a relative address as the last operand.

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Table 36. TMS370 Family Opcode/Instruction Map† (Continued)

LSN \ MSN	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
C	JNV ra 2/5	MPY Rs,A 2/46	MPY #n,A 2/45	MPY Rs,B 2/46	MPY Rs,Rd 3/48	MPY #n,B 2/45	MPY B,A 1/47	MPY #n,Rs 3/47	BR lab 3/9	BR *Rp 2/8	BR *lab[B] 3/11	RR A 1/8	RR B 1/8	RR Rd 2/6	TRAP 3 1/14	POP ST 1/8
D	JGE ra 2/5	CMP Rs,A 2/7	CMP #n,A 2/6	CMP Rs,B 2/7	CMP Rs,Rd 3/9	CMP #n,B 2/6	CMP B,A 1/8	CMP #n,Rd 3/8	CMP & lab,A 3/11	CMP *Rp,A 2/10	CMP *lab[B],A 3/13	RRC A 1/8	RRC B 1/8	RRC Rd 2/6	TRAP 2 1/14	LDSP 1/7
E	JG ra 2/5	DAC Rs,A 2/9	DAC #n,A 2/8	DAC Rs,B 2/9	DAC Rs,Rd 3/11	DAC #n,B 2/8	DAC B,A 1/10	DAC #n,Rd 3/10	CALL lab 3/13	CALL *Rp 2/12	CALL *lab[B] 3/15	RL A 1/8	RL B 1/8	RL Rd 2/6	TRAP 1 1/14	STSP 1/8
F	JLO ra 2/5	DSB Rs,A 2/9	DSB #n,A 2/8	DSB Rs,B 2/9	DSB Rs,Rd 3/11	DSB #n,B 2/8	DSB B,A 1/10	DSB #n,Rd 3/10	CALLR lab 3/15	CALLR *Rp 2/14	CALLR *lab[B] 3/17	RLC A 1/8	RLC B 1/8	RLC Rd 2/6	TRAP 0 1/14	NOP 1/7

Second byte of two-byte instructions (F4xx):

F4	8	MOVW *n[Rn] 4/15	DIV Rn.A 3/14-63
F4	9	JMPL *n[Rn] 4/16	
F4	A	MOV *n[Rn],A 4/17	
F4	B	MOV A,*n[Rn] 4/16	
F4	C	BR *n[Rn] 4/16	
F4	D	CMP *n[Rn],A 4/18	
F4	E	CALL *n[Rn] 4/20	
F4	F	CALLR *n[Rn] 4/22	

Legend:

*	=	Indirect addressing operand prefix
&	=	Direct addressing operand prefix
#	=	immediate operand
#16	=	immediate 16-bit number
lab	=	16-label
n	=	immediate 8-bit number
Pd	=	Peripheral register containing destination type
Pn	=	Peripheral register
Ps	=	Peripheral register containing source byte
ra	=	Relative address
Rd	=	Register containing destination type
Rn	=	Register file
Rp	=	Register pair
Rpd	=	Destination register pair
Rps	=	Source Register pair
Rs	=	Register containing source byte

† All conditional jumps (opcodes 01-0F), BTJO, BTJZ, and DJNZ instructions use two additional cycles if the branch is taken. The BTJO, BTJZ, and DJNZ instructions have a relative address as the last operand.

development system support

The TMS370 family development support tools include an assembler, a C compiler, a linker, a compact development tool, and an EEPROM/UVEPROM programmer.

- Assembler/linker (Part No. TMDS3740850–02 for PC)
  - Includes extensive macro capability
  - Allows high-speed operation
  - Provides format conversion utilities for popular formats.
- ANSI C Compiler (Part No. TMDS3740855–02 for PC, Part No. TMDS3740555–09 for HP700™, Sun-3™ or Sun-4™)
  - Generates assembly code for the TMS370 that can be inspected easily
  - Improves code execution speed and reduces code size with optional optimizer pass
  - Enables direct reference to the TMS370's port registers by using a naming convention
  - Provides flexibility in specifying the storage for data objects
  - Interfaces C functions and assembly functions easily
  - Includes assembler and linker
- CDT370 (compact development tool) real-time in-circuit emulation
  - Base (Part Number EDSCDT370 – for PC, requires cable)
    - Cable for 28-pin PLCC (Part No. EDSTRG28PLCCCX)
    - Cable for 28-pin DIP (Part No. EDSTRG28DILCX)
  - Includes EEPROM and EPROM programming support
  - Allows inspection and modification of memory locations
  - Allows uploading/downloading program and data memory
  - Executes programs and software routines
  - Includes 1024 samples trace buffer
  - Provides single-step executable instructions
  - Uses software breakpoints to halt program execution at selected address
- Microcontroller programmer
  - Base (Part No. TMDS3760500A – for PC, requires programmer head)
    - Single unit head for 28-pin PLCC/DIP (Part No. TMDS3780514A)
  - Personal computer based, window/function-key-oriented user interface for ease of use and rapid learning environment

HP700 is a trademark of Hewlett-Packard Company.
Sun-3 and Sun-4 are trademarks of Sun Microsystems, Incorporated.

device numbering conventions

Figure 13 illustrates the numbering and symbol nomenclature for the TMS370CxCx family.

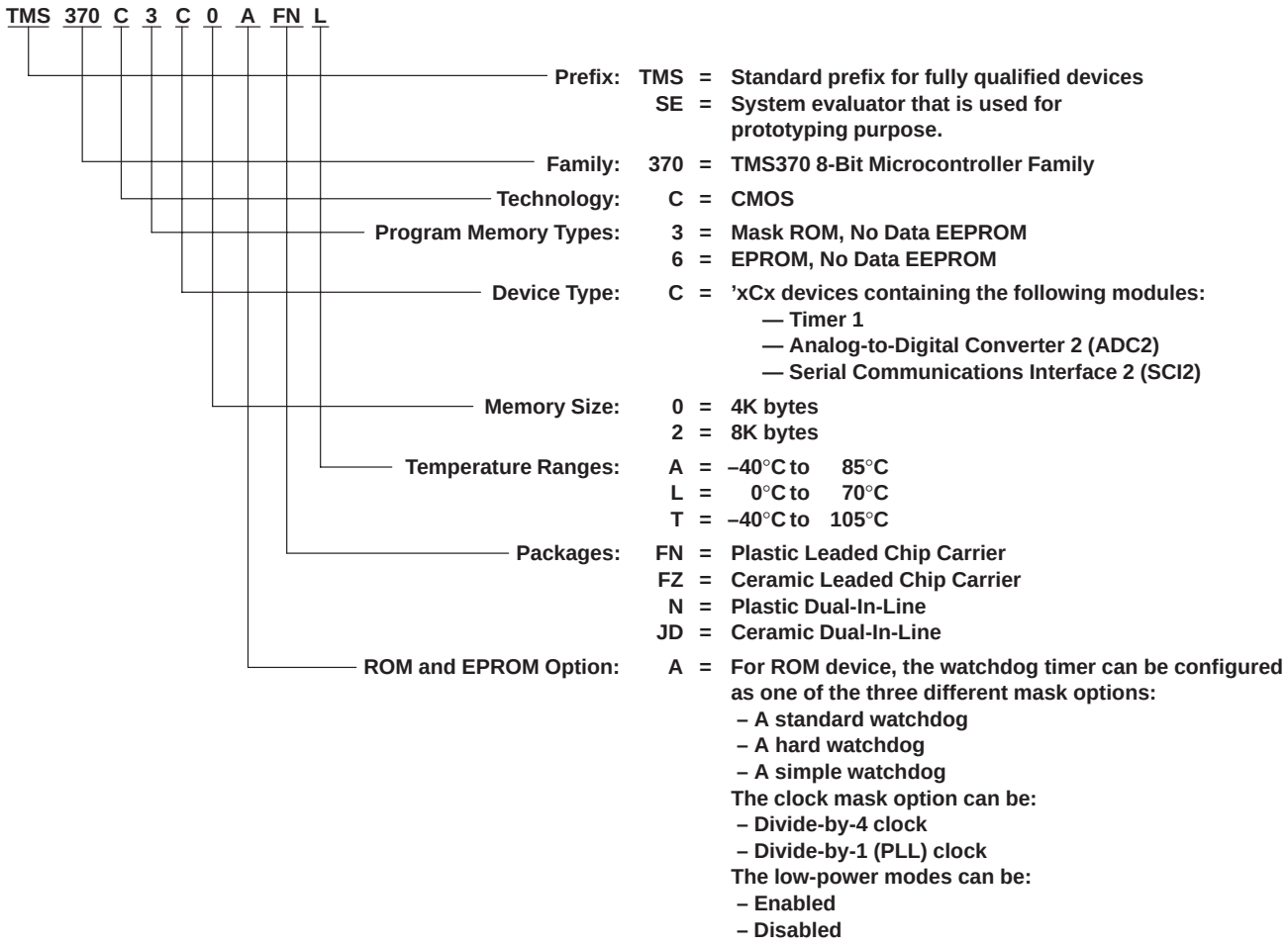


Figure 13. TMS370CxCx Family Nomenclature

device part numbers

Table 37 lists all of the 'xCx devices available. The devices' part number nomenclature is designed to assist ordering. Upon ordering, the customer must specify not only the device part number, but also the clock and watchdog timer options desired. Each device can have only one of the three possible watchdog timer options and one of the two clock options. The required options information pertains solely to orders involving ROM devices.

Table 37. Device Part Numbers

DEVICE PART NUMBERS	
FOR 28 PINS (LCC)	**FOR 28 PINS (DIP)**
TMS370C3C0AFNA TMS370C3C0AFNL TMS370C3C0AFNT	TMS370C3C0ANA TMS370C3C0ANL TMS370C3C0ANT
TMS370C6C2AFNT	TMS370C6C2ANT
SE370C6C2AFZT†	SE370C6C2AJDT†

† System evaluators are for use in prototype environment and their reliability has not been characterized.

new code release form

Figure 14 shows a sample of the new code release form.

NEW CODE RELEASE FORM
TEXAS INSTRUMENTS
TMS370 MICROCONTROLLER PRODUCTS

DATE: _____

To release a new customer algorithm to TI incorporated into a TMS370 family microcontroller, complete this form and submit with the following information:

1. A ROM description in object form on Floppy Disk, Modem XFR, or EPROM (Verification file will be returned via same media)
2. An attached specification if not using TI standard specification as incorporated in TI's applicable device data book.

Company Name: _____
Street Address: _____
Street Address: _____
City: _____ State _____ Zip _____

Customer Part Number: _____
Customer Application: _____

TMS370 Device: _____

TI Customer ROM Number: _____
(provided by Texas Instruments)

OSCILLATOR FREQUENCY

	MIN	TYP	MAX
[] External Drive (CLKIN)	_____	_____	_____
[] Crystal	_____	_____	_____
[] Ceramic Resonator	_____	_____	_____

[] Supply Voltage MIN: _____ MAX: _____
(std range: 4.5V to 5.5V)

TEMPERATURE RANGE
[] 'L': 0° to 70°C (standard)
[] 'A': –40° to 85°C
[] 'T': –40° to 105°C

SYMBOLIZATION
[] TI standard symbolization
[] TI standard w/customer part number
[] Customer symbolization
(per attached spec, subject to approval)

Contact Mr./Ms.: _____
Phone: (_____)_____ Ext.: _____

Customer Purchase Order Number: _____

Customer Print Number *Yes:____ # _____
No: ___ (Std. spec to be followed)
*If Yes: Customer must provide "print" to TI w/NCRF for approval before ROM code processing starts.

CONTACT OPTIONS FOR THE 'A' VERSION TMS370 MICROCONTROLLERS

Low Power Modes	Watchdog counter	Clock Type
[] Enabled	[] Standard	[] Standard (/4)
[] Disabled	[] Hard Enabled	[] PLL (/1)
	[] Simple Counter	

NOTE:
Non 'A' version ROM devices of the TMS370 microcontrollers will have the "Low-power modes Enabled", "Divide-by-4" Clock, and "Standard" Watchdog options. See the *TMS370 Family User's Guide* (literature number SPNU127) or the *TMS370 Family Data Manual* (literature number SPNS014B).

PACKAGE TYPE
[] 'N' 28-pin PDIP [] "FN" 44-pin PLCC
[] "FN" 28-pin PLCC [] "FN" 68-pin PLCC
[] "N" 40-pin PDIP [] "NM" 64-pin PSDIP
[] "NJ" 40-pin PSDIP (formerly known as N2)

BUS EXPANSION
[] YES [] NO

NON-STANDARD SPECIFICATIONS:
ALL NON-STANDARDS SPECIFICATIONS MUST BE APPROVED BY THE TI ENGINEERING STAFF: If the customer requires expedited production material (i.e., product which must be started in process prior to prototype approval and full production release) and non-standard spec issues are not resolved to the satisfaction of both the customer and TI in time for a scheduled shipment, the specification parameters in question will be processed/tested to the standard TI spec. Any such devices which are shipped without conformance to a mutually approved spec, will be identified by a 'P' in the symbolization preceding the TI part number.

RELEASE AUTHORIZATION:
This document, including any referenced attachments, is and will be the controlling document for all orders placed for this TI custom device. Any changes must be in writing and mutually agreed to by both the customer and TI. The prototype cycletime commences when this document is signed off and the verification code is approved by the customer.

1. Customer: _____ Date: _____

2. TI: Field Sales: _____
Marketing: _____
Prod. Eng.: _____
Proto. Release: _____

Figure 14. Sample New Code Release Form

Table 38 is a collection of all the peripheral file frames used in the ’CxCx (provided for a quick reference).

Table 38. Peripheral File Frame Compilation

PF	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
	System Configuration Registers								
P010	COLD START	**OSC POWER**	**PF AUTO WAIT**	OSC FLT FLAG	MC PIN WPO	MC PIN DATA	—	µP/µC MODE	SCCR0
P011	—	—	—	**AUTO WAIT DISABLE**	—	**MEMORY DISABLE**	—	—	SCCR1
P012	**HALT/ STANDBY**	**PWRDWN/ IDLE**	—	**BUS STEST**	**CPU STEST**	—	**INT1 NMI**	**PRIVILEGE DISABLE**	SCCR2
P013 to P016	Reserved								
P017	INT1 FLAG	INT1 PIN DATA	—	—	—	INT1 POLARITY	INT1 PRIORITY	INT1 ENABLE	INT1
P018 to P01B	Reserved								
P01C	BUSY	VPPS	—	—	—	—	W0	EXE	EPCTL
P01D P01E P01F	Reserved								
	Digital Port-Control Registers								
P020	Reserved								APORT1
P021	Port A Control Register 2 (must be 0)								APORT2
P022	Port A Data								ADATA
P023	Port A Direction								ADIR
P024 to P02B	Reserved								
P02C	Port D Control Register 1 (must be 0)		—	Port D Control Register 1 (must be 0)		—	—	—	DPORT1
P02D	Port D Control Register 2 (must be 0)†		—	Port D Control Register 2 (must be 0)†		—	—	—	DPORT2
P02E	Port D Data		—	Port D Data		—	—	—	DDATA
P02F	Port D Direction		—	Port D Direction		—	—	—	DDIR
	Timer 1 Module Register Memory Map								
	Modes: Dual-Compare and Capture/Compare								
P040	Bit 15	T1Counter MSbyte						Bit 8	T1CNTR
P041	Bit 7	T1 Counter LSbyte						Bit 0	
P042	Bit 15	Compare Register MSbyte						Bit 8	T1C
P043	Bit 7	Compare Register LSbyte						Bit 0	
P044	Bit 15	Capture/Compare Register MSbyte						Bit 8	T1CC
P045	Bit 7	Capture/Compare Register LSbyte						Bit 0	
P046	Bit 15	Watchdog Counter MSbyte						Bit 8	WDCNTR
P047	Bit 7	Watchdog Counter LSbyte						Bit 0	
P048	Bit 7	Watchdog Reset Key						Bit 0	WDRST

† To configure pin D3 as SYSCLK, set port D control register 2 = 08h.

Table 38. Peripheral File Frame Compilation (Continued)

PF	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
	Mode: Dual-Compare and Capture/Compare (Continued)								
P049	WD OVRFL TAP SEL†	WD INPUT SELECT2†	WD INPUT SELECT1†	WD INPUT SELECT0†	—	T1 INPUT SELECT2	T1 INPUT SELECT1	T1 INPUT SELECT0	T1CTL1
P04A	WD OVRFL RST ENA†	WD OVRFL INT ENA	WD OVRFL INT FLAG	T1 OVRFL INT ENA	T1 OVRFL INT FLAG	—	—	T1 SW RESET	T1CTL2
	Mode: Dual-Compare								
P04B	T1EDGE INT FLAG	T1C2 INT FLAG	T1C1 INT FLAG	—	—	T1EDGE INT ENA	T1C2 INT ENA	T1C1 INT ENA	T1CTL3
P04C	T1 MODE=0	T1C1 OUT ENA	T1C2 OUT ENA	T1C1 RST ENA	T1CR OUT ENA	T1EDGE POLARITY	T1CR RST ENA	T1EDGE DET ENA	T1CTL4
	Mode: Capture / Compare								
P04B	T1EDGE INT FLAG	—	T1C1 INT FLAG	—	—	T1EDGE INT ENA	—	T1C1 INT ENA	T1CTL3
P04C	T1 MODE = 1	T1C1 OUT ENA	—	T1C1 RST ENA	—	T1EDGE POLARITY	—	T1EDGE DET ENA	T1CTL4
	Modes: Dual-Compare and Capture/Compare								
P04D	—	—	—	—	T1EVT DATA IN	T1EVT DATA OUT	T1EVT FUNCTION	T1EVT DATA DIR	T1PC1
P04E	T1PWM DATA IN	T1PWM DATA OUT	T1PWM FUNCTION	T1PWM DATA DIR	T1IC/CR DATA IN	T1IC/CR DATA OUT	T1IC/CR FUNCTION	T1IC/CR DATA DIR	T1PC2
P04F	**T1 STEST**	**T1 PRIORITY**	—	—	—	—	—	—	T1PRI
	SCI2 Module Control Memory Map								
P050	STOP BITS	EVEN/ODD PARITY	PARITY ENABLE	ASYNC ENABLE	ADDRESS/ IDLE WUP	SCI CHAR2	SCI CHAR1	SCI CHAR0	SCICCR
P051	—	—	SCI SW RESET	CLOCK ENABLE	TXWAKE	SLEEP	TXENA	RXENA	SCICTL
P052	BAUDF (MSB)	BAUDE	BAUDD	BAUDC	BAUDB	BAUDA	BAUD9	BAUD8	BAUD MSB
P053	BAUD7	BAUD6	BAUD5	BAUD4	BAUD3	BAUD2	BAUD1	BAUD0 (LSB)	BAUD LSB
P054	TXRDY	TX EMPTY	—	—	—	—	—	SCI TX INT ENA	TXCTL
P055	RX ERROR	RXRDY	BRKDT	FE	OE	PE	RXWAKE	SCI RX INT ENA	RXCTL
P056	Reserved								
P057	RXDT7	RXDT6	RXDT5	RXDT4	RXDT3	RXDT2	RXDT1	RXDT0	RXBUF
P058	Reserved								
P059	TXDT7	TXDT6	TXDT5	TXDT4	TXDT3	TXDT2	TXDT1	TXDT0	TXBUF
P05A to P05D	Reserved								
P05E	SCITXD DATA IN	SCITXD DATA OUT	SCITXD FUNCTION	SCITXD DATA DIR	SCIRXD DATA IN	SCIRXD DATA OUT	SCIRXD FUNCTION	SCIRXD DATA DIR	SCIPC2
P05F	**SCI STEST**	**SCITX PRIORITY**	**SCIRX PRIORITY**	**SCI ESPEN**	—	—	—	—	SCIPRI

† Once the WD OVRFL RST ENA bit is set, these bits cannot be changed until a reset; this applies only to the standard watchdog and to simple counter. In the hard watchdog, these bits can be modified at any time; the WD INPUT SELECT2 bits are ignored.

Table 38. Peripheral File Frame Compilation (Continued)

PF	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
	ADC2 Module Control Registers								
P070	CONVERT START	SAMPLE START	—	REF VOLT SELECT1	REF VOLT SELECT0	—	AD INPUT SELECT1	AD INPUT SELECT0	ADCTL
P071	—	—	—	—	—	AD READY	AD INT FLAG	AD INT ENA	ADSTAT
P072	A-to-D Conversion Data Register								ADDATA
P073 to P07C	Reserved								
P07D	—	—	—	—	Port E Data Input Register				ADIN
P07E	—	—	—	—	Port E Input Enable Register				ADENA
P07F	**AD STEST**	**AD PRIORITY**	**AD ESPEN**	—	—	—	—	—	ADPRI

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 2) . . . . . –0.6 V to 7 V
Input voltage range, All pins except MC . . . . . –0.6 V to 7 V
MC . . . . . –0.6 V to 14 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) . . . . . ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) . . . . . ±20 mA
Continuous output current per buffer, I_O (V_O = 0 to V_{CC}) (see Note 3) . . . . . ±10 mA
Maximum I_{CC} current . . . . . 170 mA
Maximum I_{SS} current . . . . . – 170 mA
Continuous power dissipation . . . . . 500 mW
Operating free-air temperature range, T_A: L version . . . . . 0°C to 70°C
A version . . . . . – 40°C to 85°C
T version . . . . . – 40°C to 105°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 2. Unless otherwise noted, all voltage values are with respect to V_{SS}.
3. Electrical characteristics are specified with all output buffers loaded with specified I_O current. Exceeding the specified I_O current in any buffer can affect the levels on other buffers.

recommended operating conditions

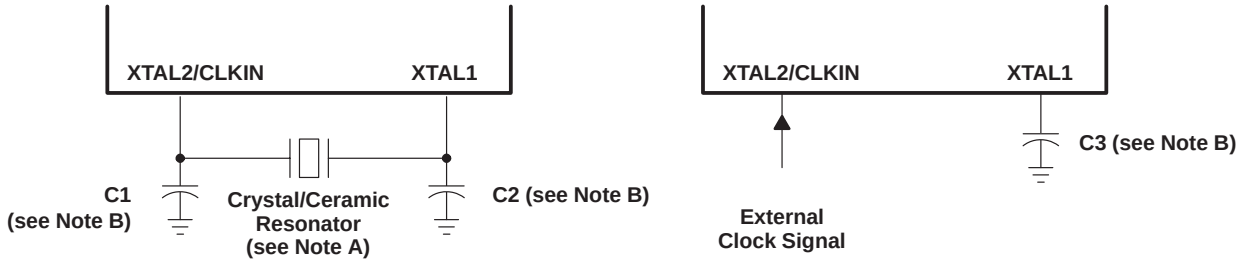
			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage (see Note 2)		4.5	5	5.5	V
	RAM data-retention supply voltage (see Note 4)		3		5.5	V
V_{IL}	Low-level input voltage	All pins except MC	V_{SS}		0.8	V
		MC, normal operation	V_{SS}		0.3	
V_{IH}	High-level input voltage	All pins except MC, XTAL2/CLKIN, and $\overline{\text{RESET}}$	2		V_{CC}	V
		XTAL2/CLKIN	0.8 V_{CC}		V_{CC}	
		$\overline{\text{RESET}}$	0.7 V_{CC}		V_{CC}	
V_{MC}	MC (mode control) voltage	EPROM programming voltage (V_{PP})	13	13.2	13.5	V
		Microcomputer	V_{SS}		0.3	
T_A	Operating free-air temperature	L version	0		70	°C
		A version	– 40		85	
		T version	– 40		105	

NOTES: 2. Unless otherwise noted, all voltage values are with respect to V_{SS}.
4. $\overline{\text{RESET}}$ must be activated externally when V_{CC} or SYSCLK is out of the recommended operating range.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

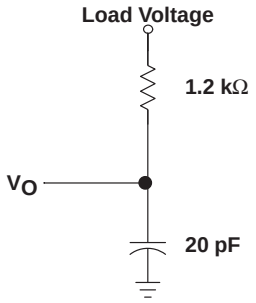
PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OL}	Low-level output voltage		I_{OL} = 1.4 mA			0.4	V
V_{OH}	High-level output voltage		I_{OH} = –50 µA	0.9 V_{CC}			V
			I_{OH} = –2 mA	2.4			
I_I	Input current	MC	0 V ≤ V_I ≤ 0.3 V			10	µA
			0.3 V < V_I ≤ 13 V			650	
			12 V ≤ V_I ≤ 13 V See Note 5			50	mA
		I/O pins	0 V ≤ V_I ≤ V_{CC}			± 10	µA
I_{OL}	Low-level output current		V_{OL} = 0.4 V	1.4			mA
I_{OH}	High-level output current		V_{OH} = 0.9 V_{CC}	– 50			µA
			V_{OH} = 2.4 V	– 2			mA
I_{CC}	Supply current (operating mode) OSC POWER bit = 0 (see Note 8)		See Notes 6 and 7 SYSCLK = 5 MHz		20	36	mA
			See Notes 6 and 7 SYSCLK = 3 MHz		13	25	
			See Notes 6 and 7 SYSCLK = 0.5 MHz		5	11	
	Supply current (STANDBY mode) OSC POWER bit = 0 (see Note 9)		See Notes 6 and 7 SYSCLK = 5 MHz		10	17	mA
			See Notes 6 and 7 SYSCLK = 3 MHz		6.5	11	
			See Notes 6 and 7 SYSCLK = 0.5 MHz		2	3.5	
	Supply current (STANDBY mode) OSC POWER bit = 1 (see Note 10)		See Notes 6 and 7 SYSCLK = 3 MHz		4.5	8.6	mA
			See Notes 6 and 7 SYSCLK = 0.5 MHz		1.5	3.0	
	Supply current (HALT mode)		See Note 6 XTAL2/CLKIN < 0.2 V		1	30	µA

NOTES: 5. Input current I_{PP} is a maximum of 50 mA only when you are programming EPROM.
6. Single chip mode, ports configured as inputs or outputs with no load. All inputs ≤ 0.2 V or ≥ V_{CC} – 0.2 V.
7. XTAL2/CLKIN is driven with an external square wave signal with 50% duty cycle and rise and fall times less than 10 ns. Current can be higher with a crystal oscillator. At 5 MHz SYSCLK, this extra current = 0.01 mA x (total load capacitance + crystal capacitance in pF).
8. Maximum operating current = 5.6 (SYSCLK) + 8 mA.
9. Maximum standby current = 3 (SYSCLK) + 2 mA. (OSC POWER bit = 0).
10. Maximum standby current = 2.24 (SYSCLK) + 1.9 mA. (OSC POWER bit = 1, only valid up to 3 MHz (SYSCLK).



NOTES: A. The crystal/ceramic resonator frequency is four times the reciprocal of the system clock period.
B. The values of C1 and C2 are typically 15 pF and the value of C3 is typically 50 pF. See the manufacturer's recommendations for ceramic resonators.

Figure 15. Recommended Crystal/Clock Connections



Case 1: $V_O = V_{OH}$ = 2.4 V; Load Voltage = 0 V
Case 2: $V_O = V_{OL}$ = 0.4 V; Load Voltage = 2.1 V

NOTE A: All measurements are made with the pin loading as shown unless otherwise noted. All measurements are made with XTAL2/CLKIN driven by an external square wave signal with a 50% duty cycle and rise and fall times less than 10 ns unless otherwise stated.

Figure 16. Typical Output Load Circuit (See Note A)

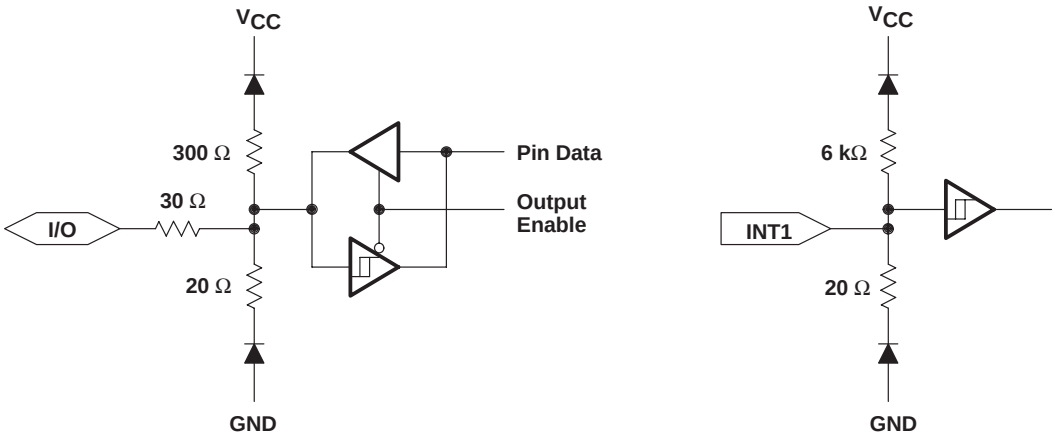


Figure 17. Typical Buffer Circuitry

PARAMETER MEASUREMENT INFORMATION

timing parameter symbology

Timing parameter symbols have been created in accordance with JEDEC Standard 100. In order to shorten the symbols, some of the pin names and other related terminology have been abbreviated as follows:

AR	Array	RXD	SCIRXD
B	Byte	SC	SYSCLK
CI	XTAL2/CLKIN	TXD	SCITXD

Lowercase subscripts and their meanings are:

c	cycle time (period)	su	setup time
d	delay time	v	valid time
f	fall time	w	pulse duration (width)
r	rise time		

The following additional letters are used with these meanings:

H	High
L	Low
V	Valid

All timings are measured between high and low measurement points as indicated in Figure 18 and Figure 19.



Figure 18. XTAL2/CLKIN Measurement Points



Figure 19. General Measurement Points

external clocking requirements for divide-by-4 clock (see Note 11 and Figure 20)

NO.	PARAMETER		MIN	MAX	UNIT
1	$t_{w(Cl)}$	Pulse duration, XTAL2/CLKIN (see Note 12)	20		ns
2	$t_{r(Cl)}$	Rise time, XTAL2/CLKIN		30	ns
3	$t_{f(Cl)}$	Fall time, XTAL2/CLKIN		30	ns
4	$t_{d(CIH-SCL)}$	Delay time, XTAL2/CLKIN rise to SYSCLK fall		100	ns
	CLKIN	Crystal operating frequency	2	20	MHz
	SYSCLK	Internal system clock operating frequency†	0.5	5	MHz

† SYSCLK = CLKIN/4

NOTES: 11. For V_{IL} and V_{IH}, refer to recommended operating conditions.

12. This pulse can be either a high pulse which extends from the earliest valid high to the final valid high in an XTAL2/CLKIN cycle, or a low pulse, which extends from the earliest valid low to the final valid low in an XTAL2/CLKIN cycle.

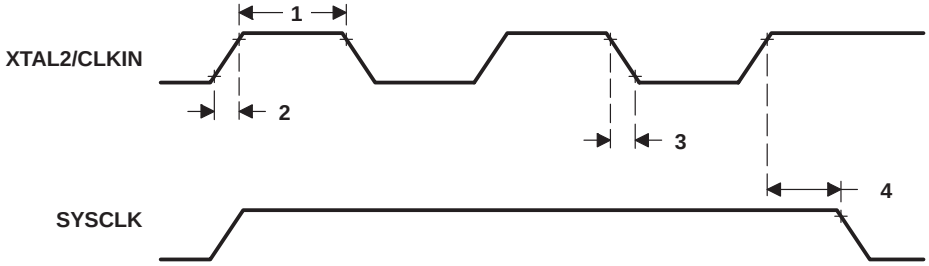


Figure 20. External Clock Timing for Divide-by-4

external clocking requirements for divide-by-1 clock (PLL) (see Note 11 and Figure 21)

NO.	PARAMETER		MIN	MAX	UNIT
1	$t_{w(Cl)}$	Pulse duration, XTAL2/CLKIN (see Note 12)	20		ns
2	$t_{r(Cl)}$	Rise time, XTAL2/CLKIN		30	ns
3	$t_{f(Cl)}$	Fall time, XTAL2/CLKIN		30	ns
4	$t_{d(CIH-SCH)}$	Delay time, XTAL2/CLKIN rise to SYSCLK rise		100	ns
	CLKIN	Crystal operating frequency	2	5	MHz
	SYSCLK	Internal system clock operating frequency‡	2	5	MHz

‡ SYSCLK = CLKIN/1

NOTES: 11. For V_{IL} and V_{IH}, refer to recommended operating conditions.

12. This pulse can be either a high pulse which extends from the earliest valid high to the final valid high in an XTAL2/CLKIN cycle, or a low pulse, which extends from the earliest valid low to the final valid low in an XTAL2/CLKIN cycle.

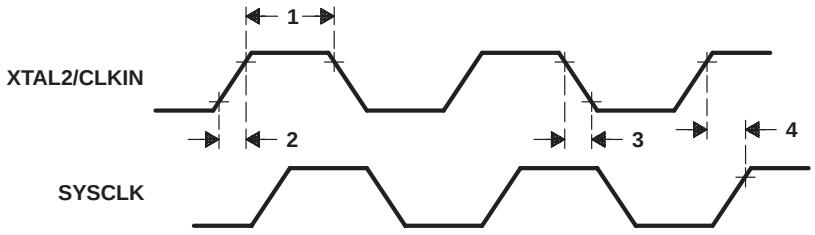


Figure 21. External Clock Timing for Divide-by-1

switching characteristics and timing requirements (see Note 13 and Figure 22)

NO.	PARAMETER			MIN	MAX	UNIT
5	t_c	Cycle time, SYSCLK (system clock)	Divide-by-4	200	2000	ns
			Divide-by-1	200	500	
6	$t_{w(SCL)}$	Pulse duration, SYSCLK low		0.5 t_c–20	0.5 t_c	ns
7	$t_{w(SCH)}$	Pulse duration, SYSCLK high		0.5 t_c	0.5 t_c + 20	ns

NOTE 13: t_c = system clock cycle time = 1/SYSCLK

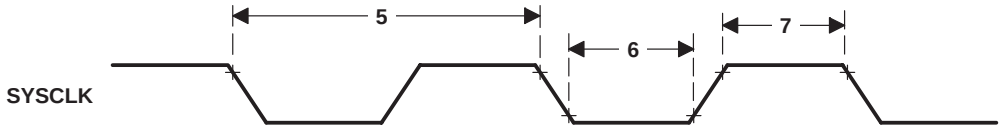


Figure 22. SYSCLK Timing

general purpose output signal switching time requirements (see Figure 23)

		MIN	NOM	MAX	UNIT
t_r	Rise time		30		ns
t_f	Fall time		30		ns

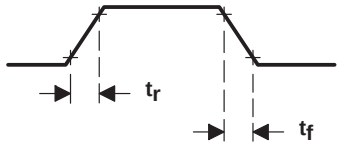


Figure 23. Signal Switching Time

recommended EPROM operating conditions for programming

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.75	5.5	6	V
V_{PP}	Supply voltage at MC pin		13	13.2	13.5	V
I_{PP}	Supply current at MC pin during programming (V_{PP} = 13 V)			30	50	mA
SYSCLK	System clock operating frequency	Divide-by-4	0.5		5	MHz
		Divide-by-1	2		5	

recommended EPROM timing requirements for programming

		MIN	NOM	MAX	UNIT
$t_{w(EPGM)}$	Pulse duration, programming signal (see Note 14)	0.40	0.50	3	ms

NOTE 14: Programming pulse is active when both EXE (EPCTL.0) and VPPS (EPCTL.6) are set.

ADC2

The ADC2 share the V_{CC} power bus for its analog and digital circuitry. All ADC2 specifications are given with respect to V_{SS} unless otherwise noted.

Resolution . . . . . 8 bits (256 values)
Monotonic . . . . . Yes
Output conversion code . . . . . 00h to FFh (00h for $V_I \le V_{SS}$; FFh for $V_I \ge V_{ref}$)
Conversion time (excluding sample time) . . . . . $164t_c$

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Analog supply voltage	4.5	5	5.5	V
V_{ref}	Non-V_{CC} reference†	2.5	V_{CC}	V_{CC} + 0.1	V
	Analog input for conversion	V_{SS}		V_{ref}	V

† V_{ref} must be stable, within ± 1/2 LSB of the required resolution, during the entire conversion time.

operating characteristics over full ranges of recommended operating conditions

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
	Absolute accuracy (see Note 15)	V_{CC} = 5.5 V, V_{ref} = 5.1 V		+1.5	LSB
	Differential/integral linearity error (see Notes 15 and 16)	V_{CC} = 5.5 V, V_{ref} = 5.1 V		±0.9	LSB
I_{CC}	Analog supply current	Converting		2	mA
		Not Converting		5	µA
I_I	Input current, AN0-AN3	0 V ≤ V_I ≤ 5.5 V		2	µA
I_{ref}	Input charge current			1	mA
Z_{ref}	Source impedance V_{ref}	SYSCLK ≤ 3 MHz		24	kΩ
		3 MHz < SYSCLK ≤ 5 MHz		10	kΩ

NOTES: 15. Absolute resolution = 20 mV. At V_{ref} = 5 V, this is 1 LSB. As V_{ref} decreases, LSB size decreases and thus absolute accuracy and differential / integral linearity errors in terms of LSBs increases.
16. Excluding quantization error of 1/2 LSB.

ADC2 (continued)

The ADC2 module allows complete freedom in design of the sources for the analog inputs. The period of the sample time is user-defined such that high-impedance sources can be accommodated without penalty to low-impedance sources. The sample period begins when the SAMPLE START bit of the ADC2 control register (ADCTL) is set to 1. The end of the signal sample period occurs when the conversion bit (CONVERT START) of the ADCTL is set to 1. After a hold time, the converter resets the SAMPLE START and CONVERT START bits, signaling that a conversion has started and the analog signal can be removed.

analog timing requirements

		MIN	MAX	UNIT
$t_{su(S)}$	Setup time, analog input to sample command	0		ns
$t_{h(AN)}$	Hold time, analog input from start of conversion	$18t_c$		ns
$t_{w(S)}$	Pulse duration, sample time per kilohm of source impedance (see Note 17)	1		μs/kΩ

NOTE 17: The value given is valid for a signal with a source impedance > 1 kΩ. If the source impedance is < 1 kΩ, use a minimum sampling time of 1 μs.

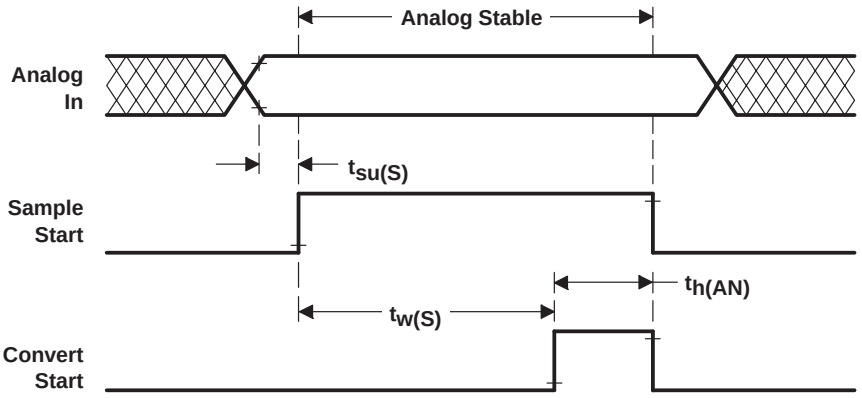


Figure 24. Analog Timing

Table 39 is designed to aid the user in referencing a device part number to a mechanical drawing. The table shows a cross-reference of the device part number to the TMS370 generic package name and the associated mechanical drawing by drawing number and name.

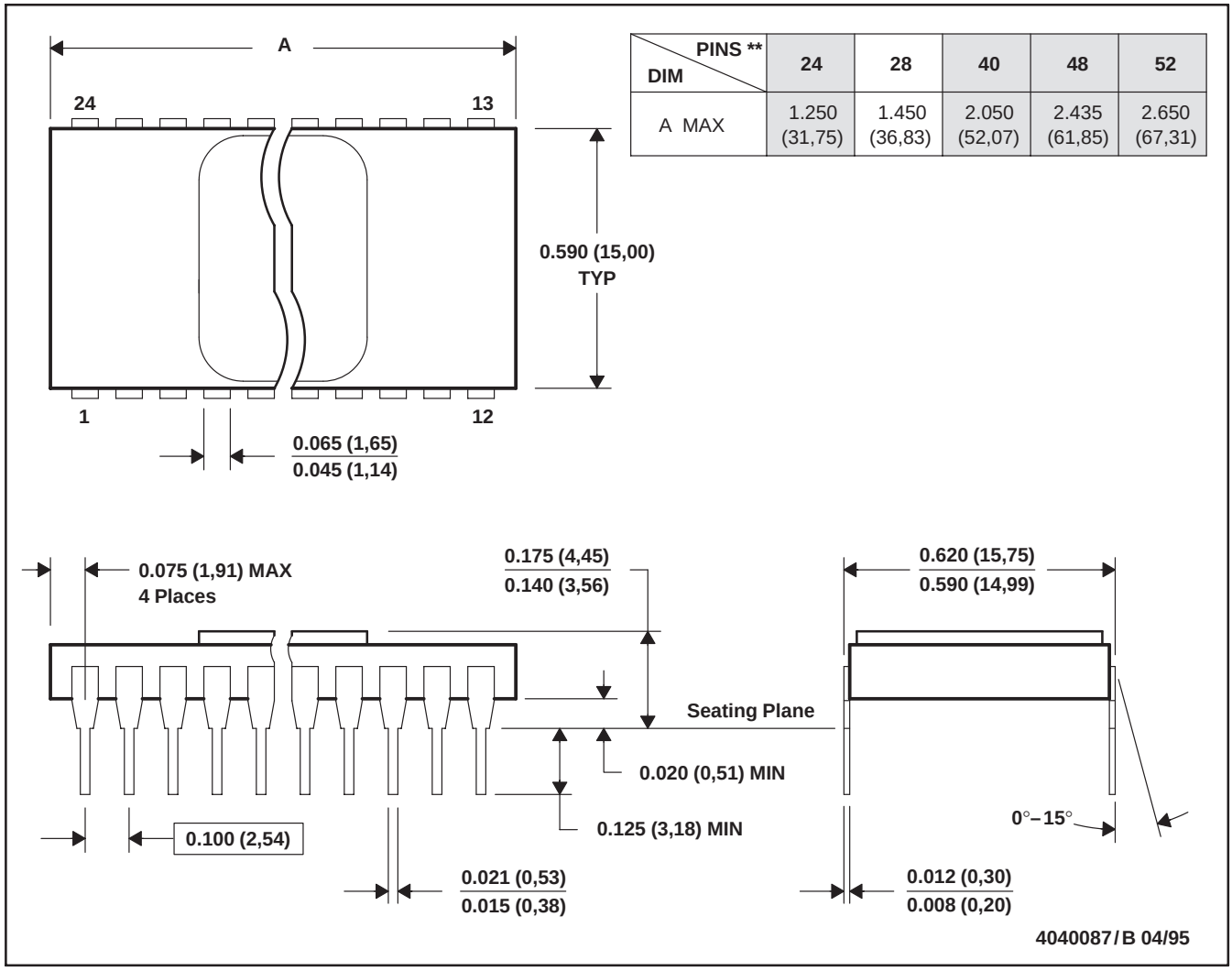
Table 39. TMS370CxCx Family Package Type and Mechanical Cross-Reference

PKG TYPE (mil pin spacing)	TMS370 GENERIC NAME	PKG TYPE NO. AND MECHANICAL NAME	DEVICE PART NUMBERS
FN – 28 pin (50–mil pin spacing)	PLASTIC LEADED CHIP CARRIER (PLCC)	FN(S-PQCC-J**) PLASTIC J-LEADED CHIP CARRIER	TMS370C3C0AFNA TMS370C3C0AFNL TMS370C3C0AFNT TMS370C6C2AFNT
FZ – 28 pin (50-mil pin spacing)	CERAMIC LEADED CHIP CARRIER (CLCC)	FZ(S-CQCC-J**) J-LEADED CERAMIC CHIP CARRIER	SE370C6C2AFZT
JD – 28 pin (70-mil pin spacing)	CERAMIC SHRINK DUAL-IN-LINE PACKAGE (CSDIP)	JD(R–CDIP–T**) CERAMIC SIDE–BRAZE DUAL–IN–LINE PACKAGE	SE370C6C2AJDT
N – 28 pin (100–mil pin spacing)	PLASTIC DUAL–IN–LINE PACKAGE (PDIP)	N(R–PDIP–T**) PLASTIC DUAL–IN–LINE PACKAGE	TMS370C3C0ANA TMS370C3C0ANL TMS370C3C0ANT TMS370C6C2ANT

MECHANICAL DATA

JD (R-CDIP-T)** **CERAMIC SIDE-BRAZE DUAL-IN-LINE PACKAGE**

24 PIN SHOWN



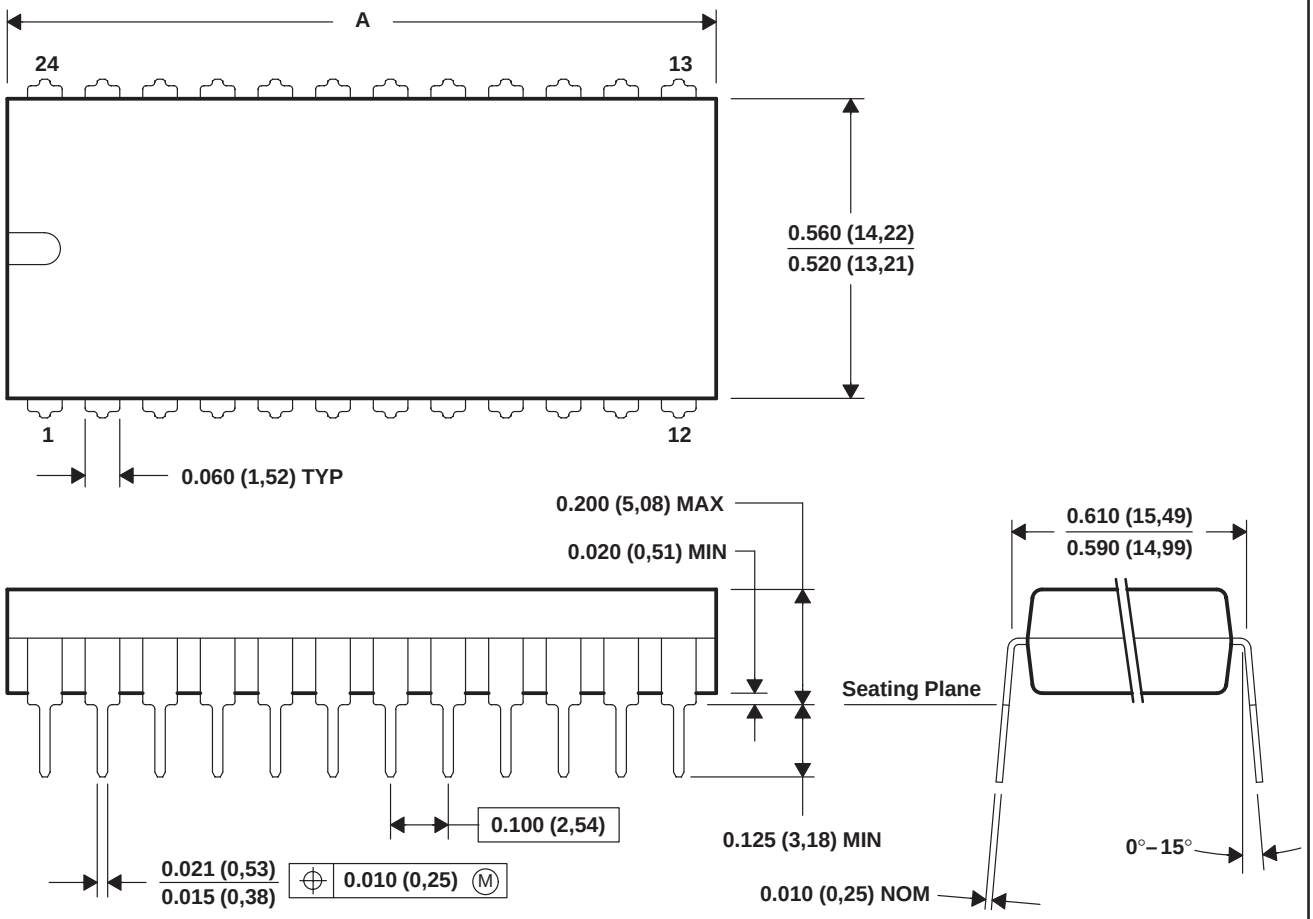
DIM \ PINS **	24	28	40	48	52
A MAX	1.250 (31,75)	1.450 (36,83)	2.050 (52,07)	2.435 (61,85)	2.650 (67,31)

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.

MECHANICAL DATA

N (R-PDIP-T)** **PLASTIC DUAL-IN-LINE PACKAGE**

24 PIN SHOWN



DIM \ PINS **	24	28	32	40	48	52
A MAX	1.270 (32,26)	1.450 (36,83)	1.650 (41,91)	2.090 (53,09)	2.450 (62,23)	2.650 (67,31)
A MIN	1.230 (31,24)	1.410 (35,81)	1.610 (40,89)	2.040 (51,82)	2.390 (60,71)	2.590 (65,79)

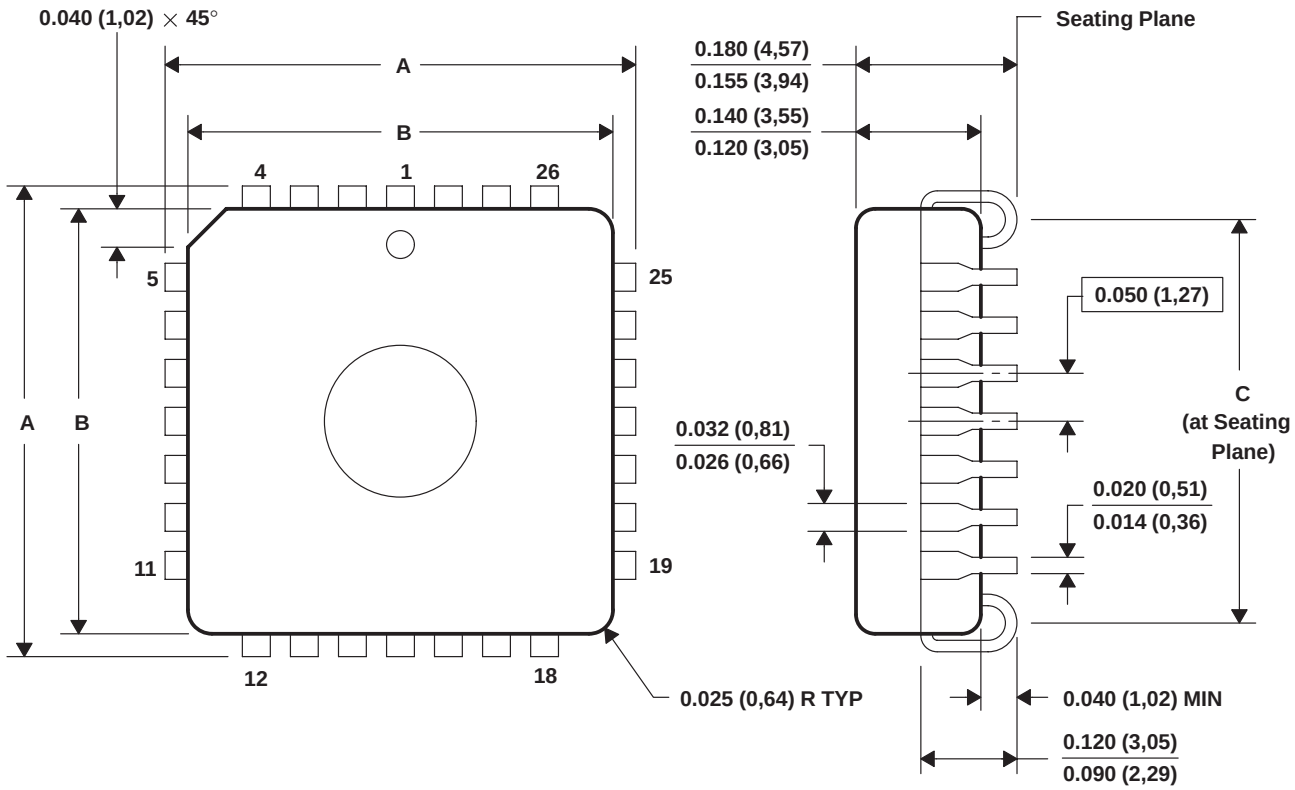
4040053/B 04/95

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-011
D. Falls within JEDEC MS-015 (32 pin only)

MECHANICAL DATA

FZ (S-CQCC-J)** **J-LEADED CERAMIC CHIP CARRIER**

28 LEAD SHOWN



JEDEC OUTLINE	NO. OF PINS**	A		B		C	
		MIN	MAX	MIN	MAX	MIN	MAX
MO-087AA	28	0.485 (12,32)	0.495 (12,57)	0.430 (10,92)	0.455 (11,56)	0.410 (10,41)	0.430 (10,92)
MO-087AB	44	0.685 (17,40)	0.695 (17,65)	0.630 (16,00)	0.655 (16,64)	0.610 (15,49)	0.630 (16,00)
MO-087AC	52	0.785 (19,94)	0.795 (20,19)	0.730 (18,54)	0.765 (19,43)	0.680 (17,28)	0.740 (18,79)
MO-087AD	68	0.985 (25,02)	0.995 (25,27)	0.930 (23,62)	0.955 (24,26)	0.910 (23,11)	0.930 (23,62)

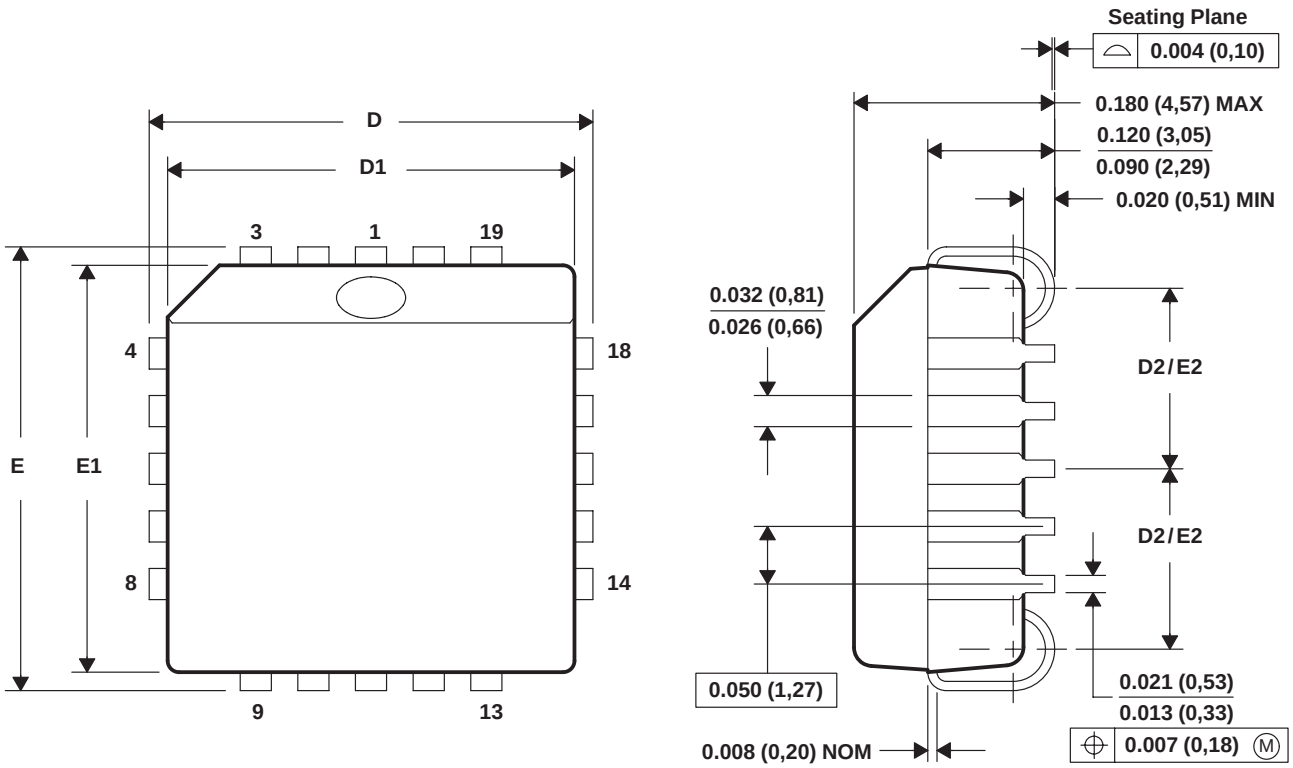
4040219/B 03/95

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.

MECHANICAL DATA

FN (S-PQCC-J)** **PLASTIC J-LEADED CHIP CARRIER**

20 PIN SHOWN



NO. OF PINS **	D/E		D1/E1		D2/E2	
	MIN	MAX	MIN	MAX	MIN	MAX
20	0.385 (9,78)	0.395 (10,03)	0.350 (8,89)	0.356 (9,04)	0.141 (3,58)	0.169 (4,29)
28	0.485 (12,32)	0.495 (12,57)	0.450 (11,43)	0.456 (11,58)	0.191 (4,85)	0.219 (5,56)
44	0.685 (17,40)	0.695 (17,65)	0.650 (16,51)	0.656 (16,66)	0.291 (7,39)	0.319 (8,10)
52	0.785 (19,94)	0.795 (20,19)	0.750 (19,05)	0.756 (19,20)	0.341 (8,66)	0.369 (9,37)
68	0.985 (25,02)	0.995 (25,27)	0.950 (24,13)	0.958 (24,33)	0.441 (11,20)	0.469 (11,91)
84	1.185 (30,10)	1.195 (30,35)	1.150 (29,21)	1.158 (29,41)	0.541 (13,74)	0.569 (14,45)

4040005/B 03/95

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-018

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SE370C6C2AFZT	OBSOLETE	JLCC	FZ	28		TBD	Call TI	Call TI
SE370C6C2AJDT	OBSOLETE	CDIP SB	JD	28		TBD	Call TI	Call TI
TMS370C3C0AFNA	PREVIEW	PLCC	FN	28		TBD	Call TI	Call TI
TMS370C3C0AFNL	PREVIEW	PLCC	FN	28		TBD	Call TI	Call TI
TMS370C3C0AFNT	PREVIEW	PLCC	FN	28		TBD	Call TI	Call TI
TMS370C3C0ANA	PREVIEW	PDIP	N	28		TBD	Call TI	Call TI
TMS370C3C0ANL	PREVIEW	PDIP	N	28		TBD	Call TI	Call TI
TMS370C3C0ANT	PREVIEW	PDIP	N	28		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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